



Architecture Overview for Debug

White Paper

Version 1.3
19 March 2021

MIPI Board Approved for Public Distribution 21 April 2021

This is an informative document, not a MIPI Specification.

Various rights and obligations that apply solely to MIPI Specifications (as defined in the MIPI Membership Agreement and MIPI Bylaws) including, but not limited to, patent license rights and obligations, do not apply to this document.

The material contained herein is not a license, either expressly or impliedly, to any IPR owned or controlled by any of the authors or developers of this material or MIPI. All materials contained herein are protected by copyright laws, and may not be reproduced, republished, distributed, transmitted, displayed, broadcast or otherwise exploited in any manner without the express prior written permission of MIPI Alliance. MIPI, MIPI Alliance and the dotted rainbow arch and all related trademarks, trade names, and other intellectual property are the exclusive property of MIPI Alliance and cannot be used without its express prior written permission.

This document is subject to further editorial and technical development.

USB Type-C™ is a trademark of the USB Implementers Forum.

NOTICE OF DISCLAIMER

The material contained herein is provided on an “AS IS” basis. To the maximum extent permitted by applicable law, this material is provided AS IS AND WITH ALL FAULTS, and the authors and developers of this material and MIPI Alliance Inc. (“MIPI”) hereby disclaim all other warranties and conditions, either express, implied or statutory, including, but not limited to, any (if any) implied warranties, duties or conditions of merchantability, of fitness for a particular purpose, of accuracy or completeness of responses, of results, of workmanlike effort, of lack of viruses, and of lack of negligence. ALSO, THERE IS NO WARRANTY OR CONDITION OF TITLE, QUIET ENJOYMENT, QUIET POSSESSION, CORRESPONDENCE TO DESCRIPTION OR NON-INFRINGEMENT WITH REGARD TO THIS MATERIAL.

IN NO EVENT WILL ANY AUTHOR OR DEVELOPER OF THIS MATERIAL OR MIPI BE LIABLE TO ANY OTHER PARTY FOR THE COST OF PROCURING SUBSTITUTE GOODS OR SERVICES, LOST PROFITS, LOSS OF USE, LOSS OF DATA, OR ANY INCIDENTAL, CONSEQUENTIAL, DIRECT, INDIRECT, OR SPECIAL DAMAGES WHETHER UNDER CONTRACT, TORT, WARRANTY, OR OTHERWISE, ARISING IN ANY WAY OUT OF THIS OR ANY OTHER AGREEMENT RELATING TO THIS MATERIAL, WHETHER OR NOT SUCH PARTY HAD ADVANCE NOTICE OF THE POSSIBILITY OF SUCH DAMAGES.

The material contained herein is not a license, either expressly or impliedly, to any IPR owned or controlled by any of the authors or developers of this material or MIPI. Any license to use this material is granted separately from this document. This material is protected by copyright laws, and may not be reproduced, republished, distributed, transmitted, displayed, broadcast or otherwise exploited in any manner without the express prior written permission of MIPI Alliance. MIPI, MIPI Alliance and the dotted rainbow arch and all related trademarks, service marks, tradenames, and other intellectual property are the exclusive property of MIPI Alliance Inc. and cannot be used without its express prior written permission. The use or implementation of this material may involve or require the use of intellectual property rights (“IPR”) including (but not limited to) patents, patent applications, or copyrights owned by one or more parties, whether or not members of MIPI. MIPI does not make any search or investigation for IPR, nor does MIPI require or request the disclosure of any IPR or claims of IPR as respects the contents of this material or otherwise.

Without limiting the generality of the disclaimers stated above, users of this material are further notified that MIPI: (a) does not evaluate, test or verify the accuracy, soundness or credibility of the contents of this material; (b) does not monitor or enforce compliance with the contents of this material; and (c) does not certify, test, or in any manner investigate products or services or any claims of compliance with MIPI specifications or related material.

Questions pertaining to this material, or the terms or conditions of its provision, should be addressed to:

MIPI Alliance, Inc.
c/o IEEE-ISTO
445 Hoes Lane, Piscataway New Jersey 08854, United States
Attn: Managing Director

Contents

Figures	v
Tables	vii
Release History	viii
1 Overview	1
1.1 Scope	1
2 Terminology	2
2.1 Definitions	2
2.2 Abbreviations	5
2.3 Acronyms	5
2.4 Use of Inclusive Language	7
3 References	8
4 Debug System	11
4.1 System Framework	11
4.2 The MIPI Debug and Test System	13
5 Debug Physical Interfaces (DPI)	15
5.1 Parallel Trace Interface (PTI) Specification	15
5.1.1 Trace and Debug Overview	15
5.1.2 Relationship to MIPI Debug Architecture	16
5.1.3 Trace Scenarios.....	17
5.1.4 Detailed Specification	21
5.2 High-speed Trace Interface (HTI) Specification	22
5.2.1 Overview	22
5.2.2 Relationship to the MIPI Debug Architecture	22
5.2.3 HTI Details	23
5.2.4 Detailed Specification	23
5.3 Debug Connector Recommendations	24
5.3.1 Dedicated Debug Connector Overview	24
5.3.2 Relationship to the MIPI Debug Architecture	24
5.3.3 Basic Debug Connectors	25
5.3.4 High-Speed Parallel Trace Connectors.....	25
5.3.5 Detailed Documentation	26
5.4 Narrow Interface for Debug and Test (NIDnT) Specification	27
5.4.1 Overview	27
5.4.2 Relationship to the MIPI Debug Architecture	27
5.4.3 NIDnT Details	28
5.4.4 Debug and Test Capabilities Supported by NIDnT Overlay Modes.....	29
5.4.5 Functional Interfaces that are NIDnT Candidates	30
5.4.6 Detailed Specification	30

6	Debug Access and Control Subsystem (DACS)	31
6.1	IEEE 1149.7 Debug and Test Interface Specification	31
6.1.1	Relationship to MIPI Debug Architecture	33
6.1.2	Detailed Specification	33
6.2	SneakPeek Specification	34
6.2.1	Relationship to MIPI Debug Architecture	34
6.2.2	Overview	34
6.2.3	Protocol Styles.....	37
6.2.4	Detailed Specifications	37
7	Debug Instrumentation and Visibility Subsystem (DIVS)	39
7.1	Instrumentation and Visibility Subsystem Overview	39
7.2	System Trace Protocol (STP) Specification	39
7.2.1	Relationship to MIPI Debug Architecture	40
7.2.2	Protocol Overview.....	40
7.2.3	Detailed Specification	42
7.3	Trace Wrapper Protocol (TWP) Specification	43
7.3.1	Overview	43
7.3.2	Relationship to MIPI Debug Architecture	44
7.3.3	TWP Features	44
7.3.4	TWP Description	45
7.3.5	Layers	45
7.3.6	Detailed Specification	45
7.4	Gigabit Trace (GbT)	46
7.4.1	Summary.....	46
7.4.2	Relationship to MIPI Debug Architecture	46
7.4.3	Gigabit Trace System Overview.....	47
7.4.4	Requirements Summary	48
7.4.5	Detailed Specification	48
7.5	STP and TWP in the DIVS	49
7.6	System Software Trace (SyS-T) Specification	51
7.6.1	Overview	51
7.6.2	Relationship to MIPI Debug Architecture	51
7.6.3	Usage.....	52
7.6.4	SyS-T Instrumentation Library.....	52
7.6.5	Detailed Specification	53
8	Debug Network Interfaces (DNI)	55
8.1	Gigabit Debug (GbD) Specification	55
8.1.1	Overview	55
8.1.2	Relationship to MIPI Debug Architecture	57
8.1.3	Detailed Specifications	57
8.2	Debug for I3C	58
8.2.1	Overview	58
8.2.2	Relationship to MIPI Debug Architecture	59
8.2.3	Target System Implementation Overview	59
8.2.4	Detailed Specification	61

Figures

Figure 1 MIPI Debug Generic System Framework.....	12
Figure 2 MIPI Debug Documentation and the Debug Architecture	13
Figure 3 Example MIPI System Overview	14
Figure 4 PTI in the MIPI Debug Architecture.....	16
Figure 5 Example System with PTI.....	17
Figure 6 PTI Layers within a System.....	18
Figure 7 Multi-Point PTI with 4-Pin Trace and Four Devices Sharing the Connector	20
Figure 8 Multi-Point PTI with 4-Pin Trace and Two Devices Sharing the Connector	21
Figure 9 HTI in the MIPI Debug Architecture	22
Figure 10 Connectors in the MIPI Debug Architecture.....	24
Figure 11 Basic Debug PCB (left) and Cable End Connector (34-pin Samtec FTSH)	25
Figure 12 Recommended Samtec QSH/QTH Connector.....	25
Figure 13 NIDnT in the MIPI Debug Architecture	27
Figure 14 Example of System with a Dedicated Debug Interface.....	28
Figure 15 Example of System with NIDnT Capability	29
Figure 16 DTS to TS Connectivity.....	32
Figure 17 IEEE 1149.7 in the MIPI Debug Architecture	33
Figure 18 SneakPeek in the MIPI Debug Architecture	34
Figure 19 Overview of SneakPeek System	35
Figure 20 SneakPeek Protocol and Network Stacks in DTS and TS	36
Figure 21 STP in the MIPI Debug Architecture	40
Figure 22 Conceptual Hierarchy of STP Major Sources and Channels	41
Figure 23 STM in a Target System.....	42
Figure 24 Example STP Packet Sequence.....	42
Figure 25 TWP in the MIPI Debug Architecture.....	44
Figure 26 Example Use Cases for Layers T1, T2 and T3.....	45
Figure 27 Gigabit Trace and the MIPI Debug Architecture	46
Figure 28 Typical GbT Configuration and Data Flow (TS)	47
Figure 29 Typical GbT Configuration and Data Flow (DTC and DTS).....	48
Figure 30 Example Trace Architecture.....	50
Figure 31 SyS-T in the MIPI Debug Architecture.....	51

Figure 32 SyS-T Instances in a Target System52
Figure 33 Gigabit Debug Functional Block Diagram55
Figure 34 GbD in a Multiple-Node Network56
Figure 35 Gigabit Debug and the MIPI Architecture57
Figure 36 Debug for I3C in the MIPI Debug Architecture.....59
Figure 37 Debug for I3C Functional Block Diagram.....60
Figure 38 Example Target System with Multiple Network Adaptors.....61

Tables

Table 1 Summary of Test/Debug Capabilities Supported by NIDnT	30
Table 2 Comparison of SneakPeek Protocol Styles.....	37

Release History

Date	Version	Description
14 February 2014	v1.0	Board approved release
29 September 2016	v1.1	Board approved release
29 August 2018	v1.2	Board approved release
19 March 2021	v1.3	Board approved release

1 Overview

1.1 Scope

1 Recent technological developments have resulted in a quantum leap in the complexity of SoCs. Systems
2 that were formerly deployed on one or more PCBs are now being instantiated as single discrete devices.
3 While this trend is in general a boon to manufacturers and consumers of various systems, it has greatly
4 increased the complexity of system debug and optimization. Signals and interfaces that used to be visible at
5 test points on a PCB are now deeply embedded inside a SoC. The use of tried and true methods of probing
6 buses and signals with dedicated Debug and Test equipment is now virtually impossible.

7 This increase in debug complexity is being addressed by IP vendors, SoC developers, OEMs and tools
8 vendors. New technologies are being deployed that provide the visibility required in these complex and
9 deeply embedded designs. In order to maximize the utility and efficiency of debug, converging on common
10 interfaces and protocols used by these new technologies is essential.

11 To meet this need, the MIPI Debug Working Group (Debug WG) are developing a portfolio of standards
12 and other documents that address the particular needs of debug. Some of the areas of focus are listed below.

- 13 • Minimizing the pin cost and increasing the performance of the basic debug interface
- 14 • Increasing the bandwidth, capability and reliability of the high-performance interfaces used to
15 export high bandwidth, unidirectional debug data (e.g., processor trace data) to the debug tools
- 16 • Deploying debug connectors that are physically robust and have the performance required for the
17 high bandwidth demands of modern debug technologies
- 18 • Developing generic trace protocols that allow many different on chip trace sources to share a
19 single trace data flow to the debug tools
- 20 • Maximizing debug visibility in fielded systems by reusing some of the functional
21 interfaces/connectors for debug
- 22 • Utilizing the new high bandwidth functional interfaces being deployed on various systems as a
23 transport for debug

24 This document provides an overview of the efforts to address these goals and provides summaries of the
25 documents that address them in detail.

2 Terminology

2.1 Definitions

26 **1149.1:** Short for IEEE 1149.1. See [IEEE01].

27 **1149.7:** Short for IEEE 1149.7. See [IEEE02].

28 **Application Function:** All functions of the TS other than Debug and Test Functions.

29 **Application Processor:** A programmable CPU (or CPU-based system on a chip (SoC) which may include
30 other programmable processors such as DSPs), primarily, but not necessarily exclusively, programmed to
31 coordinate the application processing and user interface processing.

32 **Application Software:** Used here to mean the target resident code that runs on the target processor. This
33 includes the operating system as well as the program(s) running with the OS.

34 **Basic Debug Communication:** Debug communication needed through an 1149.1 (or equivalent) port only
35 to manage basic debug communication functions such as run control, hardware breakpoints and
36 watchpoints, and examining system state.

37 **Boundary Scan:** A production test mechanism where interconnects between chips or logic blocks in an
38 SoC are verified by forcing known test patterns into the system via a serial scan interface, activating a test
39 mode, and then scanning out the resultant values to test against expected results.

40 **Built-in Self-Test (BIST):** On-chip logic function that verifies all or a portion of the internal functionality
41 of a SoC during production tests. BIST logic requires minimal interaction with external test infrastructures
42 and speeds up verification of complex SoCs.

43 **Debug:** To detect, trace, and eliminate SW mistakes. Also used to get an insight into an embedded
44 processor system for performance measurements and debug of system level hardware. Used in this
45 document in an inclusive way that encompasses stop/start/break/step debugging as well as non-halting
46 methods such as trace.

47 **Debug Access and Control Subsystem (DACS):** The subsystem that provides a path for the DTS to obtain
48 direct access to application visible system resources (registers and memory).

49 **Debug and Test Controller (DTC):** The hardware system that is responsible for managing
50 communications with a system being debugged (the Target System).

51 **Debug and Test Function:** A block of on-chip logic that carries out a debug function such as run control,
52 providing debug access to system resources, Processor Trace, or test capability.

53 **Debug and Test Interface (DTI):** The interface between the Debug and Test System (DTS) and the Target
54 System (TS). The interface enables access to basic debug communication, the trace port, streaming data
55 (input and output), and other debug or test capabilities.

56 **Debug and Test System (DTS):** The combined HW and SW system that provides a system developer
57 debug visibility and control when connected to a Target System. The system incorporates:

- 58 • A host PC, workstation or other processing system, running the debug or test software, controlling
59 the Debug and Test Controller. See also: Debug and Test Controller (DTC).
- 60 • Debugger: The debugger software, part of the Debug and Test System. It interacts with the Debug
61 and Test Controller and provides the (graphical) user interface for operating the Debug and Test
62 Controller (like commanding single step, setting breakpoints, memory display/modify, trace
63 reconstruction, etc.)

64 **Debug and Test Target (DTT):** A component in the Target System that implements one or more Debug
65 and Test Functions. The interfaces to Debug and Test Targets, where different from the DTI, are not within
66 the scope of this specification. Examples include the debug control module on a CPU, debug interface to
67 system memory, or the configuration interface to an on-chip trace module.

- 68 **Debug Instrumentation and Visibility Subsystem (DIVS):** The subsystem that provides communication
69 and storage of data generated by debug instrumentation modules (like processor and system trace) in the
70 target system.
- 71 **Debug Physical Interfaces (DPI):** The chip and board level interfaces used to connect the DTC to the on-
72 chip debug functions.
- 73 **Double Data Rate (DDR):** A parallel data interface that provides valid data on both the rising and falling
74 edge of the interface clock.
- 75 **Electrical:** The definition of:
- 76 • Signal voltage levels, current drain and drive strength on inputs, outputs, and bi-directional pins
 - 77 • Rise and fall times and expected loads for device pins.
- 78 **Function Assignment:** The mapping of functions to signals (and thus to pins as per the current Pin
79 Assignment, e.g., Debug port pin [5] = CLK = TRACECLK.)
- 80 **Function Select:** The method by which the Basic Debug Communication channel can be switched between
81 use for Debug Functions and use for operations needed to configure the debug system.
- 82 **Gigabit Trace (GbT):** A system architecture that supports transporting trace data over high-speed
83 networks and transports. See *[MIPI04a]*.
- 84 **Gigabit Debug (GbD):** A set of network-specific adaptor specifications for mapping SneakPeek and
85 Gigabit Trace to various functional networks.
- 86 **Hardware Protocol:** The signal protocol required for a Debug and Test Controller to correctly move
87 control or data information between the DTC and Target System.
- 88 **High Bandwidth Connection:** A Mating Connection, Pin Assignment and Electrical specification for full
89 functionality, high frequency, higher pin count connection between the Target System and the Debug and
90 Test Controller / TPA.
- 91 **High-speed Trace Interface (HTI):** The transport specification that defines the electrical and timing
92 characteristics of high-speed serial trace export interfaces. See *[MIPI09]*.
- 93 **IEEE 1149.7 (basic debug communication):** Enhanced IEEE1149.1 Debug and Test communication
94 standard, configurable from 4 to 2 pins. The IEEE 1149.7 interface can be viewed as providing
95 functionality enhanced compared to 1149.1 for Basic Debug Communication and test and with fewer pins.
96 A two-way communication channel for exclusive Debug and Test uses. See *[IEEE02]*.
- 97 **Intellectual Property (IP):** any patents, patent rights, trademarks, service marks, registered designs,
98 topography or semiconductor mask work rights, applications for any of the foregoing, copyrights,
99 unregistered design rights, trade secrets and know-how and any other similar protected rights in any
100 country. Any IP definition by MIPI Bylaws will supersede this local one.
- 101 **Low Pin Count Connection:** A Mating Connection, Pin Assignment and Electrical specification for Basic
102 Debug Communication and limited Trace Port functionality, lower frequency, low pin count connection
103 between the Target System and the Debug and Test Controller / TPA.
- 104 **Mating Connection:** The connector to be used, defined by specific manufacturer and part number. The
105 required keep out area for board design to enable unobstructed connector mating. The definition of cable
106 characteristics and terminations may include the characteristics of a connection from the point it leaves an
107 output buffer in a chip on the target or host side, routing on a printed circuit board on the DTC or Target
108 System side, cabling between the signal source and destination, and any connections (via connectors) in the
109 signal path.
- 110 **Min-Pin:** An interface for Basic Debug Communication with a minimal number of pins (2), using either
111 IEEE 1149.7, SWD or I3C.
- 112 **Mode Select:** A method for selecting a different Mating Connection, a different operating mode, a different
113 electrical mode or a combination of these, for example switching between 1149.1 and 1149.7.

- 114 **Narrow Interface for Debug and Test (NIDnT):** A signal-mapping specification that defines how to reuse
115 the functional interfaces commonly available on fielded systems for debug. See *[MIPI05]*.
- 116 **Nexus:** An IEEE-ISTO 5001™ standard interface for embedded processor debug. The Nexus standard
117 includes support for Basic Debug Communication as well as instruction and data tracing. See *[ISTO01]*.
- 118 **Other Debug:** Debug functions not covered by 1149.1, 1149.7 or the Trace Port for example off-chip
119 memory emulation.
- 120 **Parallel Trace Interface (PTI):** The interface specification that defines the electrical and timing
121 characteristics of trace export interfaces that consist of a single clock and multiple data signals. See
122 *[MIPI02]*.
- 123 **Pin Assignment:** The mapping of signals to pins, e.g., SIGNAL_NAME on pin number N. This may
124 include restrictions on allowable pin assignments.
- 125 **Processor Trace:** The non-intrusive capture and logging of the activity of an embedded processor and the
126 subsystem in which the processor resides. Processor trace generally consists of one or more of the
127 following trace types, but it is not limited to these:
- 128 • Instruction (PC) Trace – Application execution flow can be reconstructed by processing the logged
129 information
 - 130 • Data Trace – Data access activity is captured at the processor boundary
- 131 The captured data is encoded for efficiency and this data is stored on-chip for later upload or immediately
132 transmitted through a chip interface to an off-chip receiver.
- 133 **Return Test Clock (RTCK):** A non-standard extension to 1149.1 that provides a feedback path for pacing
134 transaction on the interface.
- 135 **Serial Wire Debug (SWD):** An interface used for Basic Debug Communication. See *[ARM01]*.
- 136 **Series Scan Topology:** A connection scheme where the control signals on the debug interfaces are
137 connected in parallel, but the data signals are daisy chained.
- 138 **Silicon Test Subsystem (STS):** This subsystem supports communication between the DTS and the on-chip
139 logic used for production test (boundary scan, BIST, etc.).
- 140 **Star Scan Topology:** A connection scheme where both the control and data signals on the debug interfaces
141 are connected in parallel.
- 142 **System Software Trace (Sys-T):** A format for transporting software traces and debugging information
143 between a target system (TS) running embedded software, and a debug and test system (DTS), typically a
144 computer running one or more debug and test applications (debuggers and trace tools).
- 145 **System Trace Module (STM):** A system trace interface with capabilities to export SW (printf type) and
146 HW generated traces (e.g., PC trace and memory dumps). Typical implementation is 4-bit parallel double
147 data rate. The STM uses a nibble-oriented protocol called STP. See *[MIPI03]*.
- 148 **System Trace Protocol (STP):** The protocol used with STM. See *[MIPI03]*.
- 149 **System on a Chip (SoC):** An electronic system in which all (or most of) the functional modules are
150 integrated on a single silicon die and packaged as a single chip.
- 151 **System Trace:** In the context of this document, system trace refers to SW Instrumentation Trace and HW
152 Instrumentation Trace.
- 153 • SW Instrumentation Trace: Message output from instrumented application code.
 - 154 • HW Instrumentation Trace: Messages triggered by transactions/events on the SoC infrastructure(s)
155 and other HW modules in the system.
- 156 **Target System (TS):** The system being debugged, up to the Debug and Test Interface (DTI). The TS might
157 be a discrete device (a chip) or a collection of 1 to N discrete devices grouped on a board or collection of
158 boards. The TS might also contain 0 to N individual Debug and Test Targets.

159 **Test Access Port (TAP):** The on-chip interface to Debug and Test resources. Both 1149.1 and 1149.7
160 support the concept of a Test Access Port.

161 **Timing:** The AC characteristics of debug signals at the pins of the target device. Includes skew, jitter, rise
162 and fall times, data/clock alignment, set-up and hold times. While this is shown to be common between all
163 connectors, there will likely be some variation, for example the Gigabit connector might not have separate
164 clock and data pins.

165 **Trace:** A form of debugging where processor or system activity is made externally visible in real-time or
166 stored and later retrieved for viewing by an applications developer, applications program, or, external
167 equipment specializing observing system activity.

168 **Trace Channel:** A group of one or more signals and a clock that move trace information from the TS to the
169 DTS. There may be more than one Trace Channel between the TS and DTS.

170 **Trace Data Protocol:** The implementation-specific encoding of a particular type of trace by a particular
171 module.

172 **Trace Port:** An output port for the transmission of real-time data indicating the operation of the target (e.g.,
173 program execution and/or data bus transactions). Data transmitted across the Trace Port may be generated
174 by hardware, software instrumentation, or by a mixture of the two. This does not include trace collected on-
175 chip for later upload.

176 **Trace Port Analyzer (TPA):** An external hardware unit for collecting data transmitted from the Trace Port.
177 The data might be stored locally in real time before uploading to the host debug tools for later analysis by
178 the user, e.g., a logic analyzer or a unit customized to record trace information would both qualify.

179 **Trace Wrapper Protocol (TWP):** A protocol that wraps trace from different sources into a single stream
180 for simultaneous capture by a single TPA. See *[MIPI04]* and *[MIPI04a]*.

181 **Trigger:** An indication that a specific system event has occurred. A trigger may be an input to the TS, a
182 signal within the TS, or an output from the TS. The response to the trigger is determined by the entity to
183 which the trigger is sent.

2.2 Abbreviations

184 e.g. For example (Latin: *exempli gratia*)
185 i.e. That is (Latin: *id est*)

2.3 Acronyms

186 AC Alternating Current
187 BIST Built-in Self-Test
188 CCC Common Command Code
189 CPU Central Processing Unit
190 DACS Debug Access and Control Subsystem
191 DDR Double Data Rate
192 DFT Design for Test
193 DIP Data Integrity Package
194 DIVS Debug Instrumentation and Visibility Subsystem
195 DNI Debug Network Interfaces
196 DPI Debug Physical Interfaces

197	DSP	Digital Signal Processor
198	DTC	Debug and Test Controller
199	DTI	Debug and Test Interface
200	DTS	Debug and Test System
201	DTT	Debug and Test Target
202	GbD	Gigabit Debug
203	GbT	Gigabit Trace
204	HTI	High-speed Trace Interface
205	HW	Hardware
206	I3C	Improved Inter Integrated Circuit
207	ID	Identifier
208	IEEE	Institute of Electrical and Electronics Engineers
209	IP	Intellectual Property
210	IPS	Internet Protocol Sockets
211	IPR	Intellectual Property Rights
212	ISTO	Industry Standards and Technology Organization
213	JTAG	Joint Test Action Group
214	microSD	Micro Secure Digital
215	MMC	MultiMediaCard
216	NIDnT	Narrow Interface for Debug and Test
217	nTRST	Not Test Reset
218	OFM	Original Functional Mode
219	OS	Operating System
220	PC	Personal Computer or Program Counter
221	PCB	Printed Circuit Board
222	PHY	Physical Interface
223	POR	Power on Reset
224	PTI	Parallel Trace Interface
225	RF	Radio Frequency
226	RTCK	Return Test Clock
227	SIM	Subscriber Identity Module
228	SoC	System on a Chip
229	SPP	SneakPeek Protocol
230	SPTB	SneakPeek Transfer Block
231	STM	System Trace Module

232	STP	System Trace Protocol
233	STS	Silicon Test Subsystem
234	SW	Software
235	SWD	Serial Wire Debug
236	SyS-T	System Software Trace
237	TAP	Test Access Port
238	TCK	Test Clock
239	TCKC	Test Clock Compact
240	TCP	Transmission Control Protocol
241	TDI	Test Data Input
242	TDIC	Test Data Input Compact
243	TDO	Test Data Output
244	TDOC	Test Data Output Compact
245	TDP	Trace Data Protocol
246	TMS	Test Mode Select
247	TMSC	Test Mode Select Compact
248	TPA	Trace Protocol Analyzer
249	TS	Target System
250	TWP	Trace Wrapper Protocol
251	UDP	User Datagram Protocol
252	USB	Universal Serial Bus
253	WG	Working Group

2.4 Use of Inclusive Language

254 The MIPI Alliance is committed to the use of inclusive language in its specifications and documentation.
 255 Terms such as “master” and “slave” are being replaced with better, more descriptive terms and the MIPI
 256 Alliance is actively updating its documentation to use the new inclusive language. This document will no
 257 longer include these non-inclusive terms and the reader will notice the new language.

258 Note that at the time of publication, not all the documents referenced in this document were updated. The
 259 table below is a list of the legacy terms that have been updated in this document with the new inclusive
 260 language.

Referenced Specification	Legacy Term	New Term
Debug for I3C	Master	Controller
	Multi-Mastering	Multiple Controller-capable
	Slave	Target
STP	Master	Major Source

261

3 References

- 262 **Note:**
- 263 *Public Release Editions are available for most of the following MIPI Alliance adopted specifications,*
- 264 *see links in respective sections.*
- 265 [MIP101] *MIPI Alliance Recommendation for Debug and Trace Connectors*, version 1.10.00 and
- 266 higher, MIPI Alliance, Inc., 16 March 2011.
- 267 [MIP102] *MIPI Alliance Specification for Parallel Trace Interface (PTISM)*, version 2.0, MIPI
- 268 Alliance, Inc., 3 May 2011.
- 269 [MIP103] *MIPI Alliance Specification for System Trace Protocol (STPSM)*, version 2.2, MIPI
- 270 Alliance, Inc., 21 August 2015.
- 271 [MIP104] *MIPI Alliance Specification for Trace Wrapper Protocol (TWPSM)*, version 1.00.00, MIPI
- 272 Alliance, Inc., 23 February 2010.
- 273 [MIP104a] *MIPI Alliance Specification for Trace Wrapper Protocol (TWPSM)*, version 1.1, MIPI
- 274 Alliance, Inc., 3 September 2014.
- 275 [MIP105] *MIPI Alliance Specification for Narrow Interface for Debug and Test (NIDnTSM)*, version
- 276 1.2, MIPI Alliance, Inc., 17 August 2017.
- 277 [MIP106] *MIPI Alliance Specification for SneakPeekSM Protocol (SPPSM)*, version 2.0, MIPI
- 278 Alliance, Inc., 21 May 2019.
- 279 [MIP107] *MIPI Alliance Specification for Gigabit Debug for USB*, version 1.1, MIPI Alliance, Inc.,
- 280 12 October 2017.
- 281 [MIP108] *MIPI Alliance Specification for Gigabit Debug for Internet Protocol Sockets*, version 1.0,
- 282 MIPI Alliance, Inc., 20 May 2016.
- 283 [MIP109] *MIPI Alliance Specification for High-Speed Trace Interface (HTISM)*, version 1.0, MIPI
- 284 Alliance, Inc., 10 March 2016.
- 285 [MIP110] *MIPI Alliance Specification for System Software Trace (Sys-TSM)*, version 1.0, MIPI
- 286 Alliance, Inc., 1 December 2017.
- 287 [MIP111] *MIPI System Software Trace (MIPI Sys-T) – Example Code*, [https://github.com/MIPI-](https://github.com/MIPI-Alliance/public-mipi-sys-t)
- 288 [Alliance/public-mipi-sys-t](https://github.com/MIPI-Alliance/public-mipi-sys-t), MIPI Alliance, Inc., last accessed 19 March 2021.
- 289 [MIP112] *MIPI Alliance Specification for Debug for I3C*, version 1.0, MIPI Alliance, Inc.,
- 290 21 April 2020.
- 291 [MIP113] *MIPI Alliance Specification I3CSM*, version 1.1, MIPI Alliance, Inc., 27 November 2019.
- 292 [MIP114] *MIPI Alliance Specification I3C BasicSM*, version 1.0, MIPI Alliance, Inc., 19 July 2018.
- 293 [IEEE01] IEEE Std 1149.1TM-2013, *Standard for Test Access Port and Boundary-Scan*
- 294 *Architecture*, Institute of Electrical and Electronic Engineers, 2013.
- 295 [IEEE02] IEEE Std 1149.7TM-2009, *Standard for Reduced-Pin and Enhanced-Functionality Test*
- 296 *Access Port and Boundary Scan Architecture*, Institute of Electrical and Electronic
- 297 Engineers, 2009.
- 298 [ISTO01] IEEE-ISTO 5001TM-2012, *The Nexus 5001 ForumTM Standard for a Global Embedded*
- 299 *Processor Debug Interface*, version 3.0.1, IEEE- Industry Standards and Technology
- 300 Organization, 2012.
- 301 [ARM01] *ARM[®] CoreSightTM Architecture Specification*, version 3.0, ARM Limited, 2017.

- 302 [AUR01] *Aurora 8B/10B Protocol Specification*, SP002 (v2.3), Xilinx, Inc., 145
303 [http://www.xilinx.com/support/documentation/ip_documentation/aurora_8b10b_protocol](http://www.xilinx.com/support/documentation/ip_documentation/aurora_8b10b_protocol_spec_sp002.pdf)
304 [_spec_sp002.pdf](http://www.xilinx.com/support/documentation/ip_documentation/aurora_8b10b_protocol_spec_sp002.pdf), 1 October 2014.
- 305 [USB01] *USB 3.1 Device Class Specification for Debug Device*, Revision 1.0, <http://www.usb.org>,
306 14 July 2015.

This page intentionally left blank.

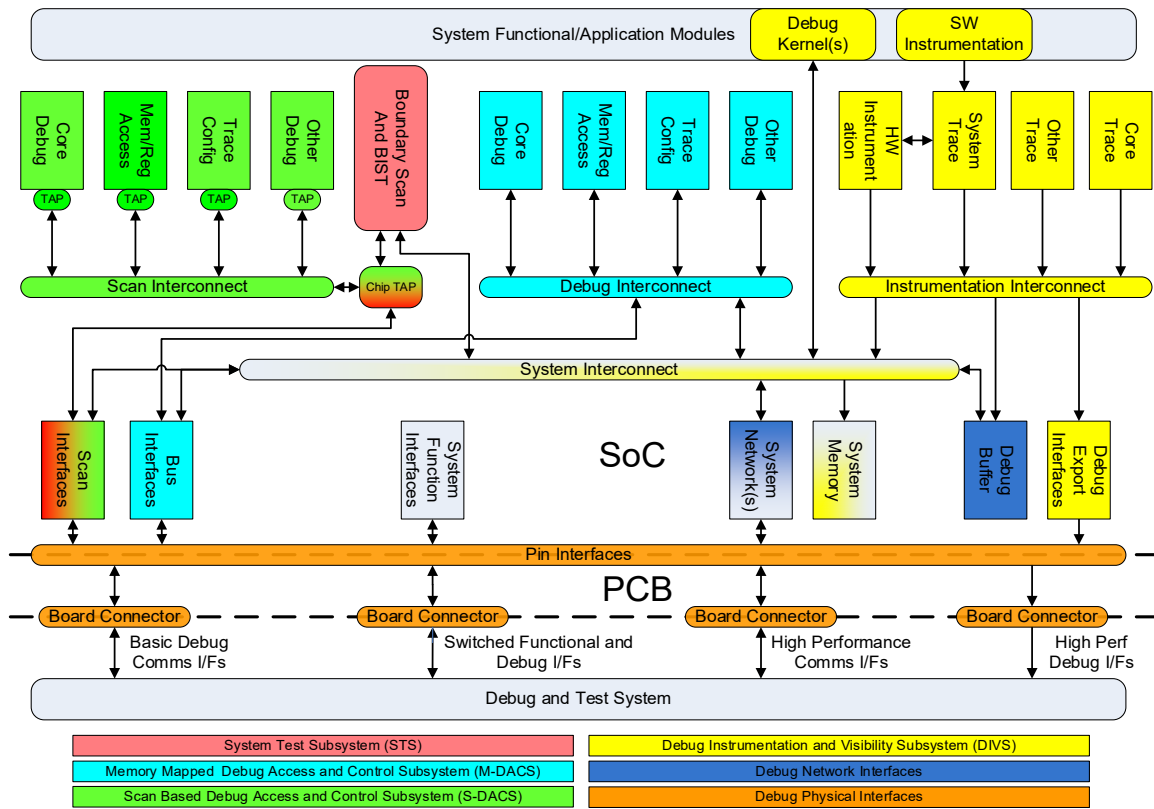
4 Debug System

4.1 System Framework

307 The modern systems on a chip often have complex Debug and Test architectures. In a simplistic view, the
308 modern SoC Debug and Test architecture can be broken down into the following major subsystems:

- 309 • **Debug Access and Control Subsystem (DACS)** – This subsystem provides a path for the DTS to
310 obtain direct access to application visible system resources (registers and memory). It also
311 provides bidirectional communication for configuration and control of debug specific modules in
312 the TS. The communication between the debug and the DACS is generally implemented via one of
313 the following (this is not an exhaustive list):
 - 314 • Serial scan via a dedicated Debug and Test interface on the device
 - 315 • Memory mapped using a dedicated debug interconnect or in some cases the application visible
316 system interconnect
 - 317 • A proprietary communication protocol and interface on the device boundary
- 318 • **Debug Instrumentation and Visibility Subsystem (DIVS)** – This subsystem provides
319 communication and storage of data generated by debug instrumentation modules (like processor
320 and system trace) in the target system. DIVS communication path to the DTS is usually via high-
321 speed serial or trace interfaces and is generally unidirectional.
- 322 • **System Test Subsystem (STS)** – This subsystem supports communication between the DTS and
323 the on-chip logic used for production test (boundary scan, BIST, etc.). Access to the STS is
324 generally accomplished via serial scan.
- 325 • **Debug Physical Interfaces (DPI)** – The physical interfaces that support debug at the SoC
326 boundary and on the PCB.
- 327 • **Debug Network Interfaces (DNI)** – The internal interfaces that allow debug and trace data to be
328 transmitted to and from the DTS on functional networks. This communication is with dedicated
329 intelligent resources (sometimes called the *Debug Butler*) that possibly:
 - 330 • Enable *bare metal* debug on systems where the normal functional communication management
331 is not yet functioning
 - 332 • Allow debug to minimize or eliminate the use of functional resources for managing debug
333 communications

334 **Figure 1** provides a top-level view of how all the pieces of the Debug and Test architecture are integrated
 335 on a device.



336

Figure 1 MIPI Debug Generic System Framework

4.2 The MIPI Debug and Test System

337 The MIPI Debug WG effort does not address all the functional blocks in the generic framework. The
 338 Debug WG standards and recommendations focus on device and board interfaces and protocols. There is
 339 also an effort to standardize on communications for debug instrumentation (i.e., trace protocols), but with a
 340 generic approach that maintains compatibility with protocols that already exist. **Figure 2** illustrates the
 341 areas of the framework that are targeted by the various MIPI Debug specifications and recommendations
 342 addressed in this document.

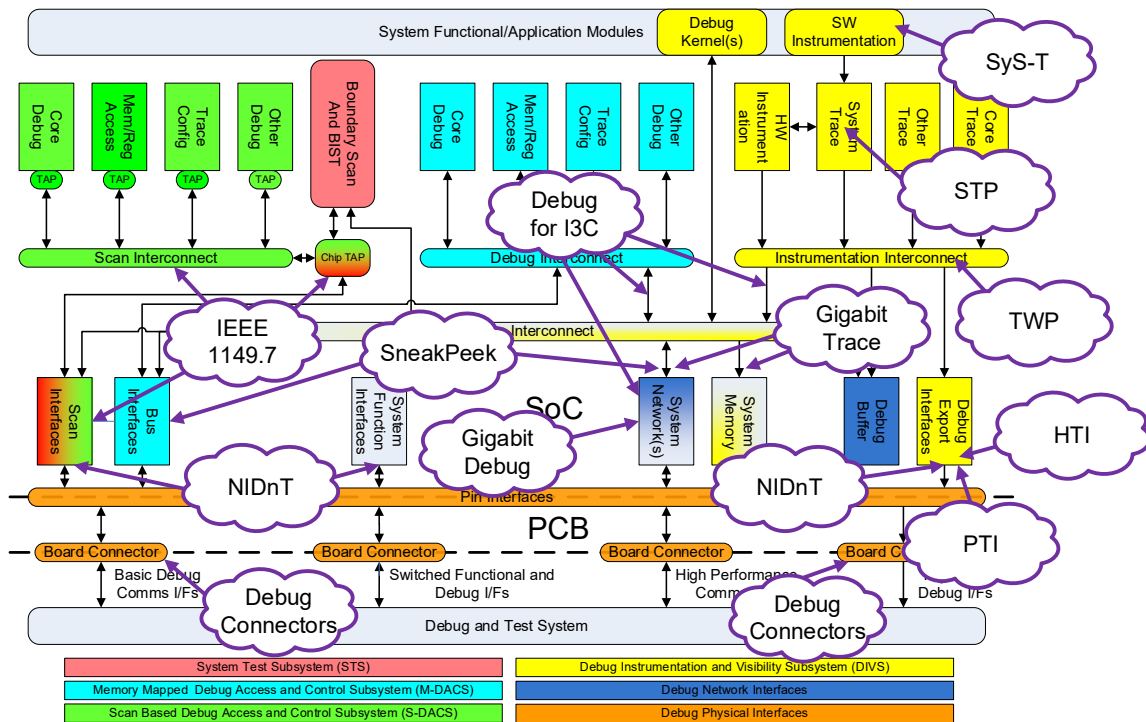
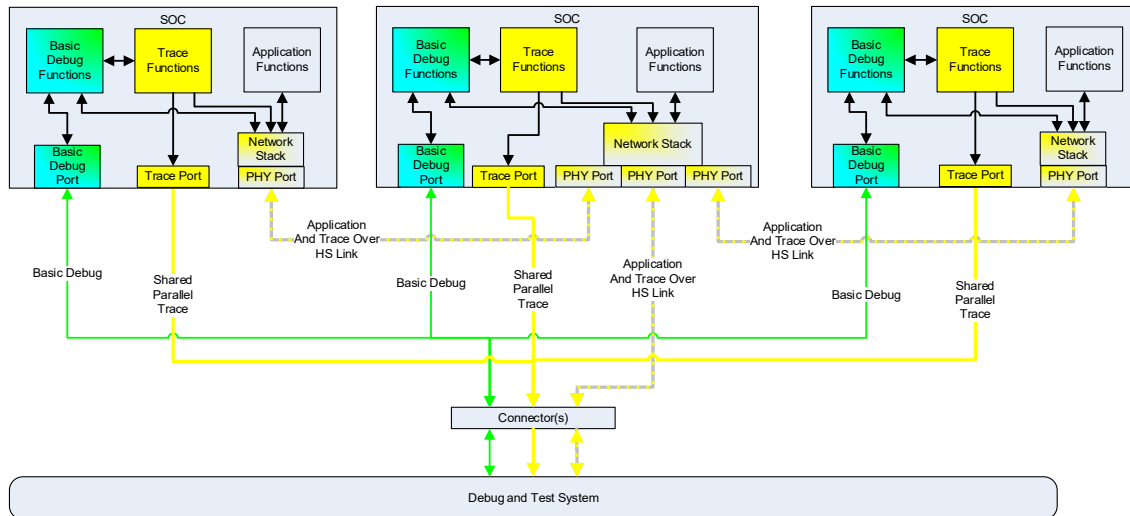


Figure 2 MIPI Debug Documentation and the Debug Architecture

344 **Figure 3** shows a more detailed block diagram showing how the generic debug framework can be realized
 345 across an entire multiple-chip system. The devices share the basic debug, trace and functional interfaces.
 346 Basic run control can be provided via the shared debug connection. Trace transport can utilize a shared link
 347 dedicated to trace or a standard application visible network. In all cases, the footprint of the debug interface
 348 to the tools is greatly reduced.



349

Figure 3 Example MIPI System Overview

5 Debug Physical Interfaces (DPI)

5.1 Parallel Trace Interface (PTI) Specification

5.1.1 Trace and Debug Overview

350 It has become an accepted axiom that as the complexity of an embedded system increases, the need for
351 system designers and developers to obtain visibility into the behavior of the system increases
352 proportionally. One of the most common methods for providing this visibility is to provide a streaming
353 interface on an embedded System on a Chip. This interface can be used to export data about system
354 functionality and behavior to a host system for analysis and display. Since the data exported on this
355 interface often allows developers to reconstruct (or “trace”) some portion of system activity, these types of
356 interface have commonly been referred to as Trace Interfaces or Trace Ports. Examples of trace data
357 include:

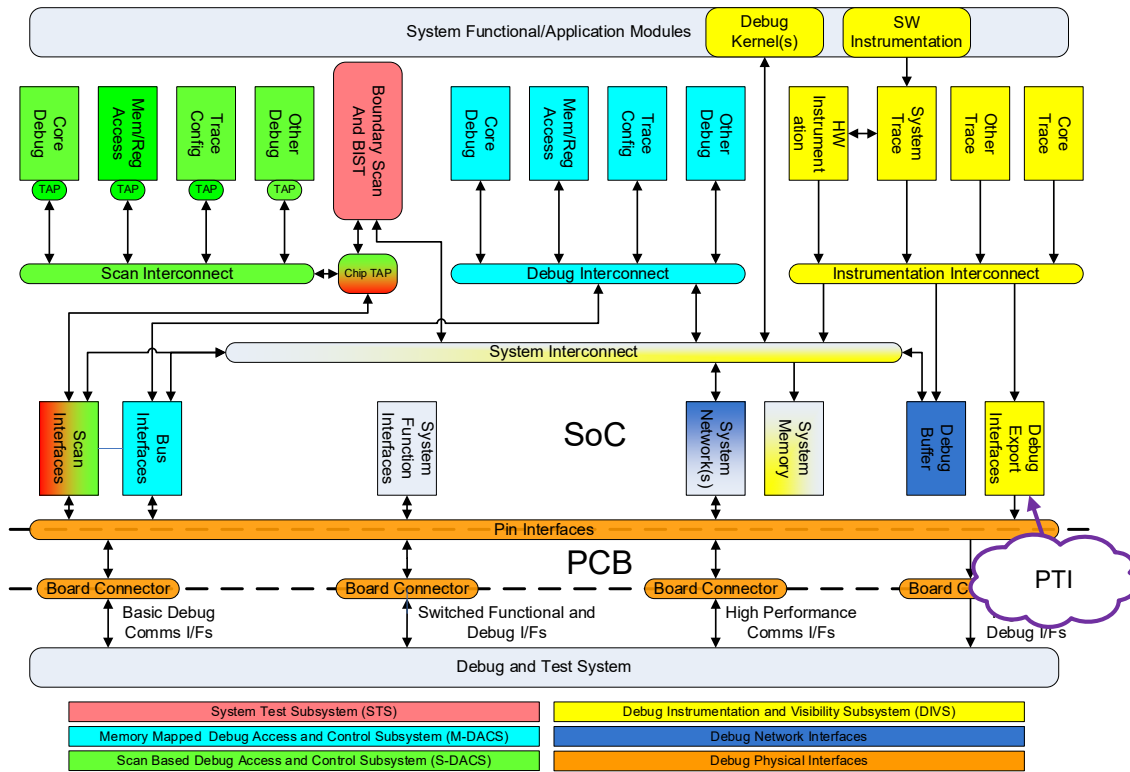
- 358 • The instruction execution sequence for one or more embedded processors. This is commonly
359 referred to as Program Counter (PC) Trace.
- 360 • Data bus transactions made by an embedded processor core. This is commonly referred to as Data
361 Trace.
- 362 • Snapshots of transactions on the system interconnect(s). This is commonly referred to as System
363 Trace.
- 364 • Streaming output from instrumented application code. This is commonly referred to as
365 Instrumentation Trace.

366 The bandwidth requirements for the common trace functions listed above often compel system designers to
367 implement the trace interface as a parallel interface with multiple data signals and a clock. For purposes of
368 this document, the trace interface will subsequently be referred to as the Parallel Trace Interface or PTI.

5.1.2 Relationship to MIPI Debug Architecture

369
370

Figure 4 shows the standard MIPI debug architecture highlighting the functional areas addressed by the PTI specification.



371

Figure 4 PTI in the MIPI Debug Architecture

5.1.3 Trace Scenarios

372 A typical embedded system may have one or more HW modules that produce trace data. The typical flow is
373 outlined below and illustrated in **Figure 5**.

- 374 • Debug and Test Targets (DTTs) reside in the Target System (TS).
- 375 • Trace modules inside a DTT contain one or more HW sub-modules that capture the system
376 transactions with the required data. See the Trace Collect block in **Figure 5**.
- 377 • One or more HW modules encode or compress the data into an implementation specific
378 encoding(s). These encoding(s) are called the Trace Data Protocols (TDPs). See the Trace Format
379 block in **Figure 5**.
- 380 • One or more HW modules export the encoded data to the DTC using device pins. The interface
381 used to transfer this data is the Parallel Trace Interface or PTI. See the Trace Export block in
382 **Figure 5**.
- 383 • The DTC captures the data.
- 384 • The data is decoded and analyzed using the DTS.

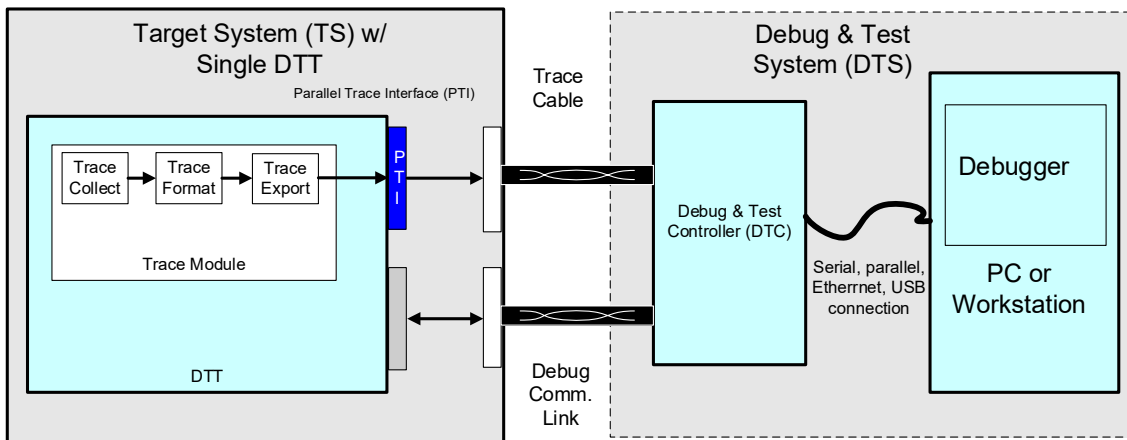


Figure 5 Example System with PTI

386 Note that only HW modules directly responsible for producing the data and clock of a PTI are required to
387 implement a PTI. **Figure 6** shows how the PTI implementation is dependent upon system configuration.

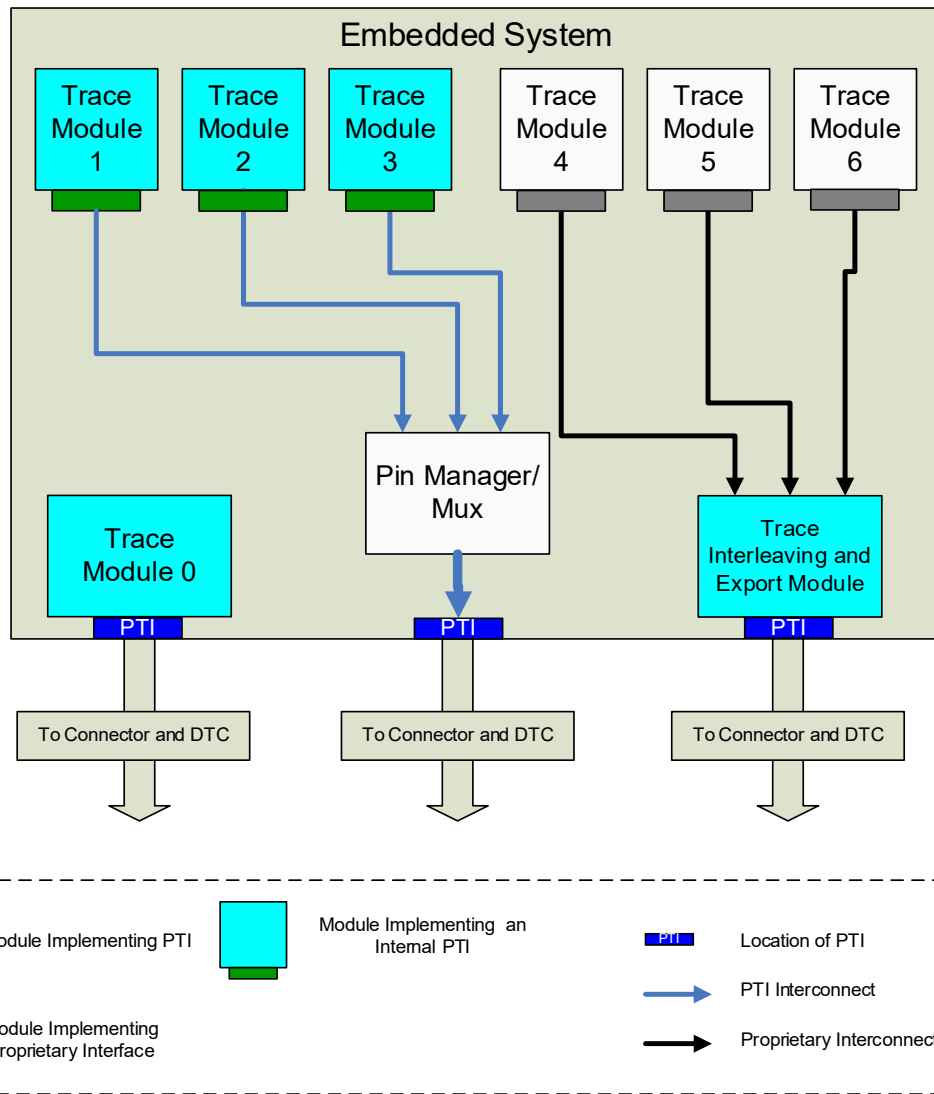


Figure 6 PTI Layers within a System

389 The scenario for Trace Module 0 is reasonably straightforward. The module itself is directly connected to a
390 dedicated PTI on the device boundary and the module is responsible for implementing the PTI.

391 The scenario for Trace Modules 1–3 is slightly more complex. Here multiple modules export trace through
392 a device level pin manager or mux. This management logic is only responsible for controlling which pins
393 on the device PTI are assigned to the device internal trace clients. It does not produce the data and clock
394 signals for the PTI but only routes them from the various trace modules. Thus, the individual trace modules
395 are required to implement the PTI. Since the pin manager routes the internal PTI signals to the device
396 boundary, there is also a PTI at the device pins.

397 The scenario for Trace Modules 4–6 shows a system where multiple trace modules provide data over a
398 proprietary trace interconnect. This system allows data to be combined or interleaved in some fashion
399 before export. The interleaving and export module implements the PTI and the individual trace modules
400 communicate using implementation specific protocols that are beyond the scope of this document.

5.1.3.1 Multi-Point Trace Connections

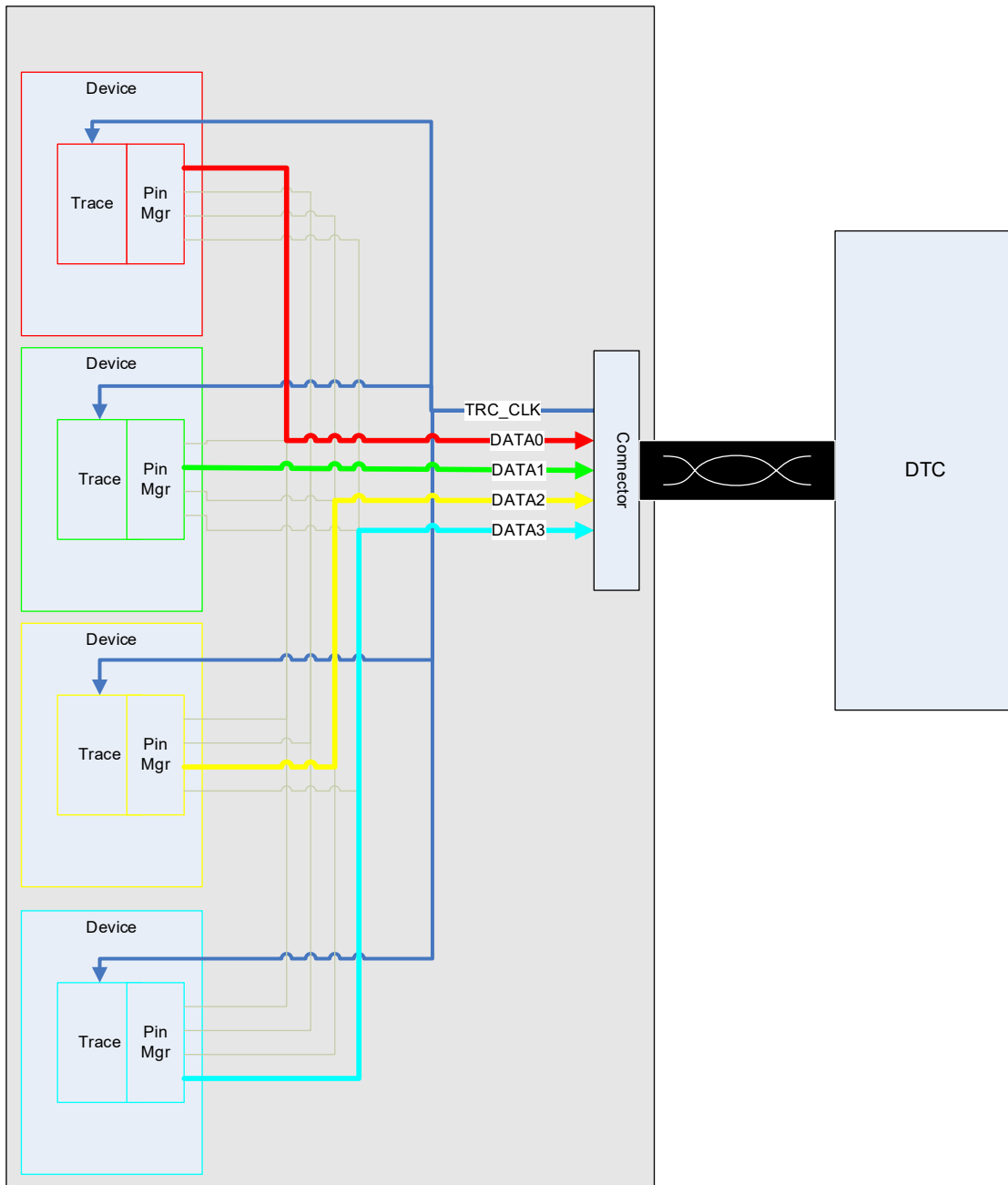
401 Version 2 of the PTI specification expands the interface description to include a shared trace connection
402 where multiple PTI interfaces are merged through a single connector on a PCB board. Multi-point PTIs are
403 very useful for supporting trace on fielded systems that have multiple trace-enabled ASICs but only a single
404 connector (with limited data pins) for interfacing to an external DTC. A standard example would be a
405 mobile terminal with an application and modem SoC and a single MIPI NIDnT connection.

406 Devices can be configured to drive data on a subset of the PTI signals on their boundaries. The PTI signals
407 are merged at the connector, but only one PTI is driving any given data signal. The clock for all the
408 interfaces is supplied from an external source (generally the DTC). *Figure 7* shows an example with four
409 devices (each with 4-pin PTIs) sharing a connector with each of them only exporting on a single pin.

410 A similar configuration is shown in *Figure 8*, but in this scenario only two devices are active and the port is
411 shared as 3 pins and 1 pin. These are just examples, and the multi-point routing scheme defined in this
412 document supports varying PTI widths and numbers of devices.

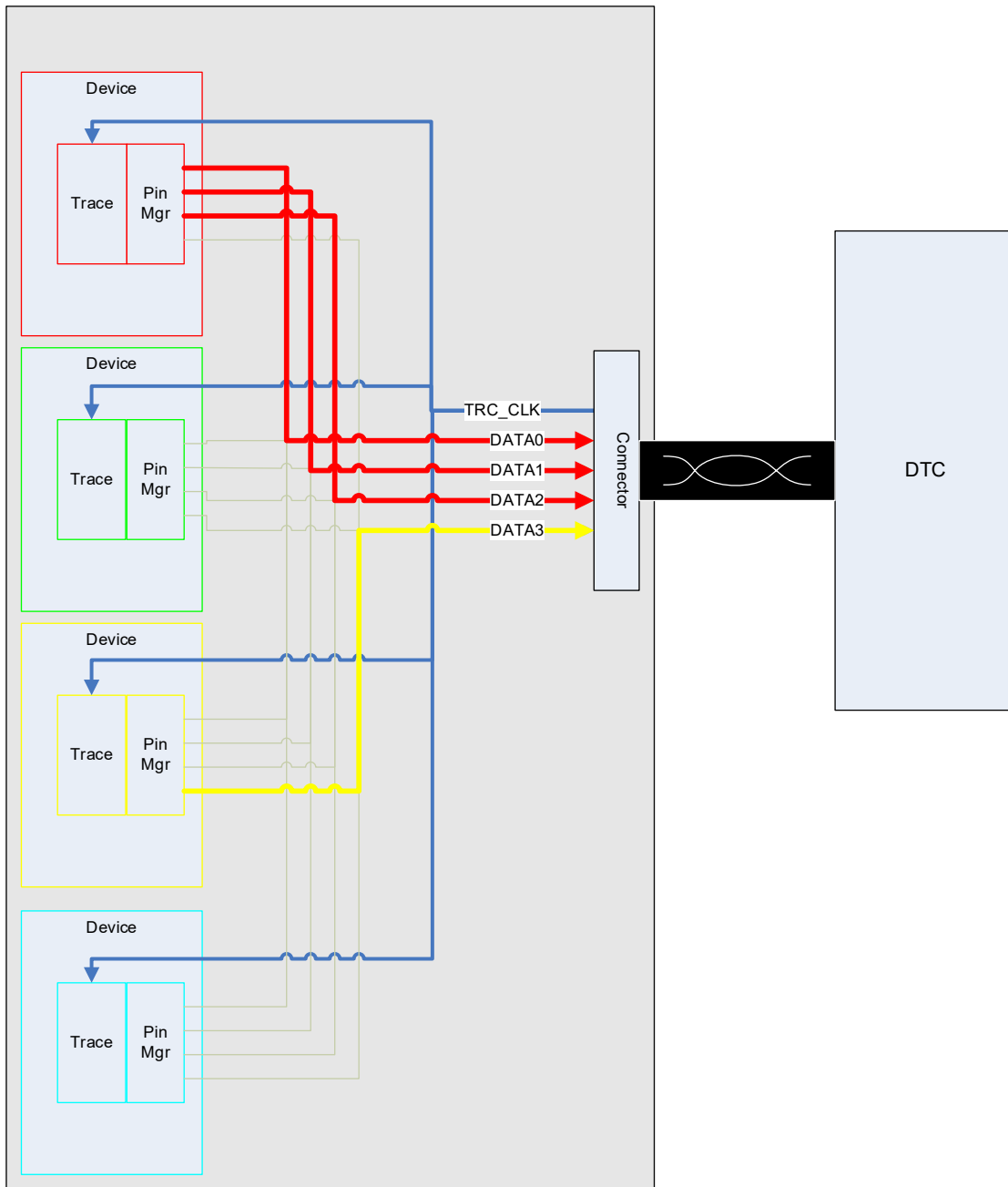
413 Providing these enhanced features requires new operating modes for the clock and data portions of a PTI.

- 414 • Clock Modes
 - 415 • PTI-out-clock Mode: The PTI sources the clock along with the data
 - 416 • PTI-in-clock Mode: The clock for the PTI is an input to the module driving the PTI data
- 417 • Data Modes
 - 418 • Point-to-point Data Mode: Data indexes are fixed on the PTI
 - 419 • Multi-point Data Mode: Data indexes may shift across the PTI



420

Figure 7 Multi-Point PTI with 4-Pin Trace and Four Devices Sharing the Connector



421

Figure 8 Multi-Point PTI with 4-Pin Trace and Two Devices Sharing the Connector

5.1.4 Detailed Specification

422 For details of the MIPI PTI, consult the document: MIPI Alliance Specification for Parallel Trace Interface,
423 *[MIP102]*. This specification is available to MIPI members and to the public through the MIPI website. The
424 public version of the specification can be found at: <http://resources.mipi.org/mipi-pti-download>.

5.2 High-speed Trace Interface (HTI) Specification

5.2.1 Overview

425 Transferring data off-chip from high performance embedded microprocessor cores requires a data port with
 426 sufficient trace data bandwidth. Parallel port implementations such as MIPI Parallel Trace Interface (PTI),
 427 *[MIP102]*, employ a clock synchronous parallel interface, using as many as 32 parallel data lines to provide
 428 the required bandwidth. Increasing CPU clock speeds and use of multiple processor cores demand
 429 increasing data port bandwidth, while at the same time the number of I/O pins used for the data port is
 430 being reduced to facilitate lower cost and a higher level of SOC/ASIC integration.

431 MIPI High-speed Trace Interface (HTI) is a serial implementation of the data port, taking advantage of
 432 available high-speed serial interface technology used in interfaces such as PCI Express®, DisplayPort™,
 433 HDMI®, or USB, provides higher transmit bandwidth with fewer I/O pins compared with a parallel
 434 implementation. Unlike protocol specifications in the MIPI Gigabit Debug portfolio, such as *[MIP108]*,
 435 HTI is not designed to be used over the high-level protocols implemented by interfaces such as PCI
 436 Express, but is intended to re-use the low-level physical high-speed portions of those interfaces, in a bare-
 437 metal environment.

5.2.2 Relationship to the MIPI Debug Architecture

438 **Figure 9** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
 439 HTI specification.

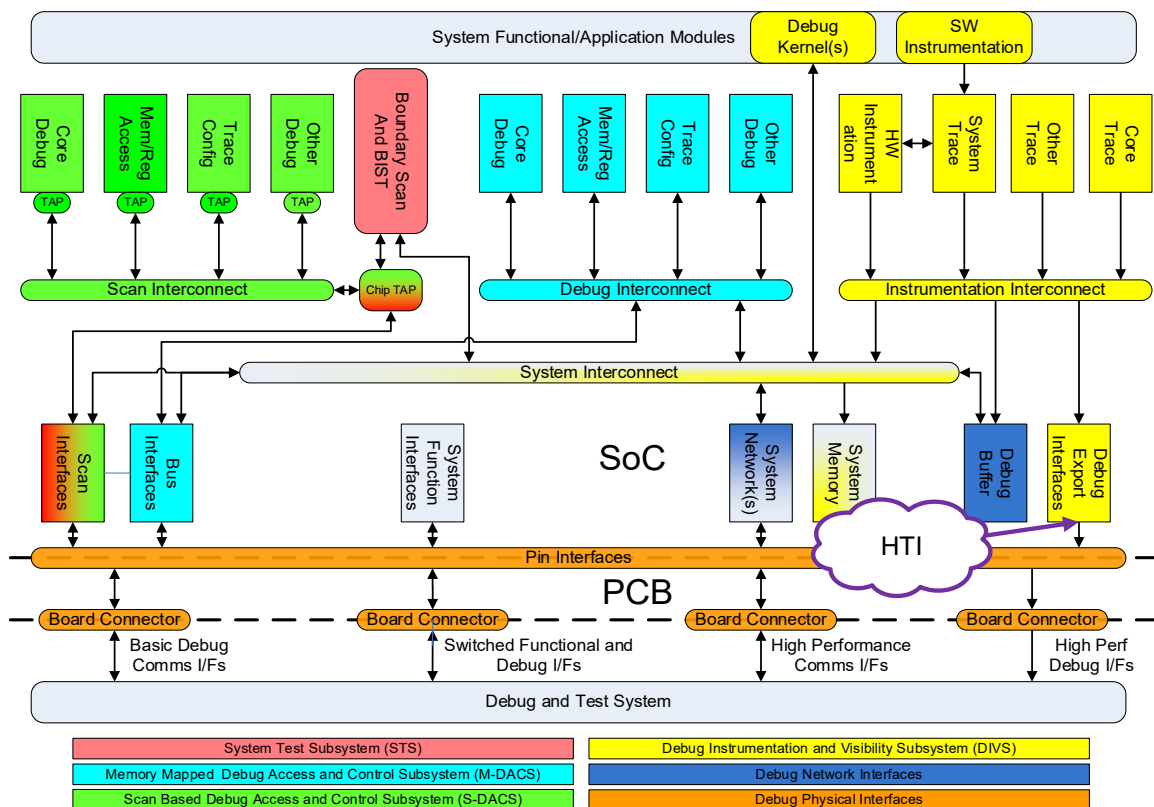


Figure 9 HTI in the MIPI Debug Architecture

440

5.2.3 HTI Details

441 HTI defines a method to transport a single stream of trace information over a channel consisting of one to
442 eight high-speed serial lanes, using the Aurora 8B/10B protocol [*AUR01*]. HTI uses the serial simplex
443 mode of Aurora to transmit data in one direction from TS to DTS.

444 The HTI specification supports transmission of either the MIPI STP [*MIPI03*] protocol or MIPI TWP
445 [*MIPI04a*] protocol over an HTI channel.

446 The HTI specification consists of the following aspects:

- 447 • The LINK layer, which defines how the trace is packaged into the Aurora 8B/10B protocol.
- 448 • The PHY layer, which defines the electrical and clocking characteristics.
- 449 • A programmer's model for controlling HTI and providing status information.

450 In addition to the trace information, the HTI LINK layer provides the ability to include:

- 451 • Optional CRC data, to assist in detecting errors in the trace transmission.
- 452 • Optional User Flow Control messages, to indicate additional information about the trace data
453 stream.

5.2.4 Detailed Specification

454 For details on HTI, consult the MIPI Alliance Specification for High-speed Trace Interface (HTI),
455 [*MIPI09*]. This specification is available to MIPI members and to the public through the MIPI website. The
456 public version of the specification can be found at: <http://resources.mipi.org/mipi-hti-download>.

5.3 Debug Connector Recommendations

5.3.1 Dedicated Debug Connector Overview

457 Board developers, debug tools vendors and test tool vendors all benefit when the number of connectors and
 458 connector pin mappings used to support Debug and Test is minimized. To this end, MIPI Alliance is
 459 promoting a set of connectors and mappings that address a wide variety of debug use scenarios.

5.3.2 Relationship to the MIPI Debug Architecture

460 *Figure 10* shows the standard MIPI debug architecture highlighting the functional areas addressed by the
 461 connector recommendation.

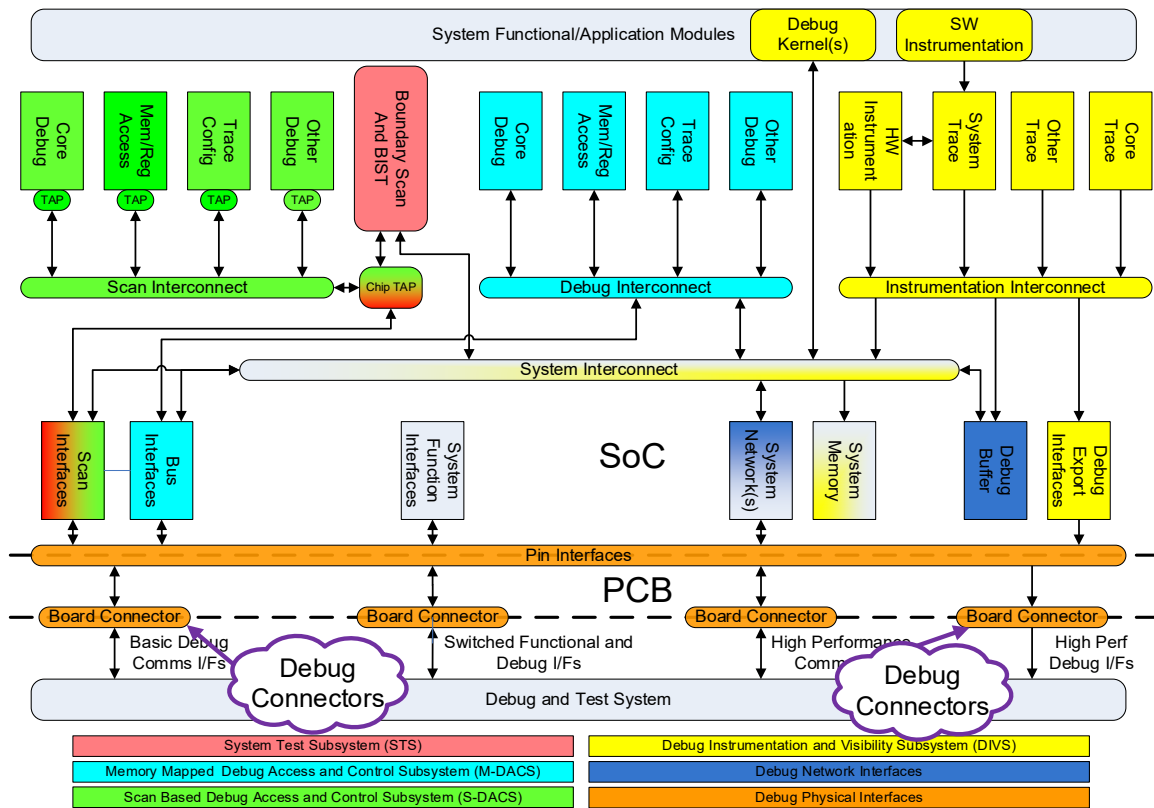
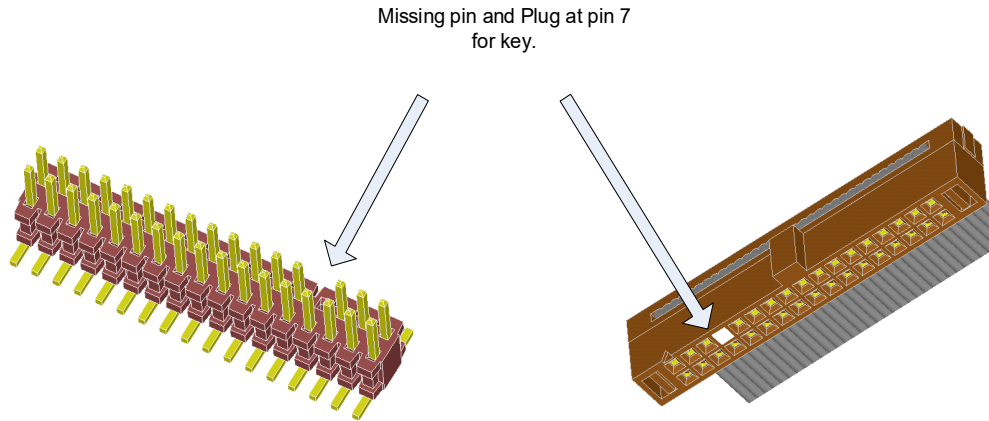


Figure 10 Connectors in the MIPI Debug Architecture

5.3.3 Basic Debug Connectors

463 As the connector was not part of the original IEEE 1149.1 JTAG standard, a large number of different
464 JTAG connectors have emerged. The MIPI recommendation of standard connectors promotes convergence
465 toward a minimum set of debug connectors. The scalable 0.05 inch Samtec FTSH connector family
466 provides a cheap, small and robust target connection and is available in many variants (including lockable
467 ones) from multiple connector vendors. The pin-out allows scaling of the debug connection to meet
468 different requirements. This includes very small footprint connections (down to 10 pins), legacy JTAG
469 support (including vendor specific pins) and system level trace support (STM).



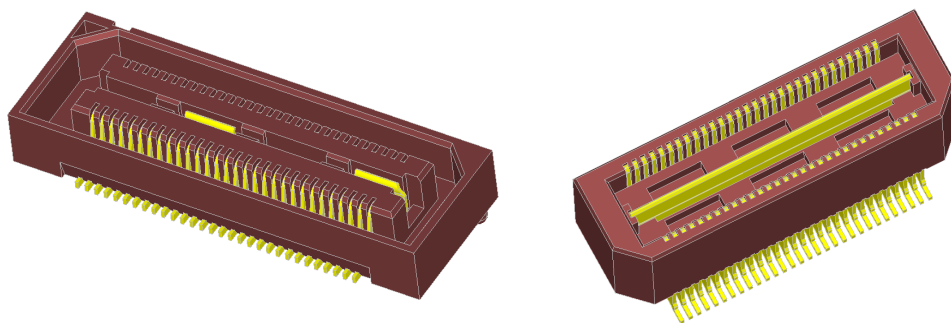
470 **Figure 11 Basic Debug PCB (left) and Cable End Connector (34-pin Samtec FTSH)**

5.3.4 High-Speed Parallel Trace Connectors

471 Many debug tools vendors support target systems with high-speed trace interfaces. These tools utilize a
472 number of different mating connectors.

473 The *MIPI Alliance Recommendation for Debug and Trace Connectors, [MIPI01]*, document defines two
474 connectors for supporting high-speed trace and basic debug. The first connector is only intended for
475 backwards-compatible designs. The second connector is recommended for new designs. The goal is to have
476 this recommendation define a “de facto” industry standard for the trace connection and thus lessen the
477 burden on target system and tools developers that need to support a large number of different mating
478 connections.

479 The recommended trace connector is a 60 pin Samtec QSH/QTH connector. The signal to pin mapping,
480 which is defined in the recommendation, supports one run control and several trace configurations. The
481 different trace configurations use up to 40 data signals and up to 4 clock signals. To minimize complexity,
482 the recommendation defines four standard configurations with one, two, three or four trace channels of
483 varying width.



484 **Figure 12 Recommended Samtec QSH/QTH Connector**

5.3.5 Detailed Documentation

485 For details of the MIPI recommended connectors and connector pin mappings, consult the document: MIPI
486 Alliance Recommendation for Debug and Trace Connectors, *[MIPI01]*. This document is available to MIPI
487 members and to the public through the MIPI website. The public version of the specification can be found
488 at: <https://mipi.org/sites/default/files/MIPI-Alliance-Recommendation-Debug-Trace-Connectors.pdf>.

5.4 Narrow Interface for Debug and Test (NIDnT) Specification

5.4.1 Overview

489 The MIPI Debug Working Group has standardized a way to utilize functional interfaces for debug or test.
490 This technology is called NIDnT (Narrow Interface for Debug and Test). It allows better debug support in
491 production or near-production units.

492 NIDnT technology defines low pin count, reliable, and high performance, debug interfaces that can be used
493 in deployed systems. These interfaces provide access to basic debug, trace of application activity, and HW
494 test capability by reusing already existing functional interfaces. In some cases, these interfaces are
495 accessible at the packaged boundary. This technology provides the means to use functional interfaces for
496 either functional or debug purposes. One or more functional interfaces (e.g., MMC card slot for trace and
497 USB for basic debug) may be used to provide debug capability. NIDnT technology does not aim to replace
498 current technologies such as debugging via a serial interface (e.g., GDB using a UART, or on-device debug
499 agent).

5.4.2 Relationship to the MIPI Debug Architecture

500 **Figure 13** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
501 NIDnT specification.

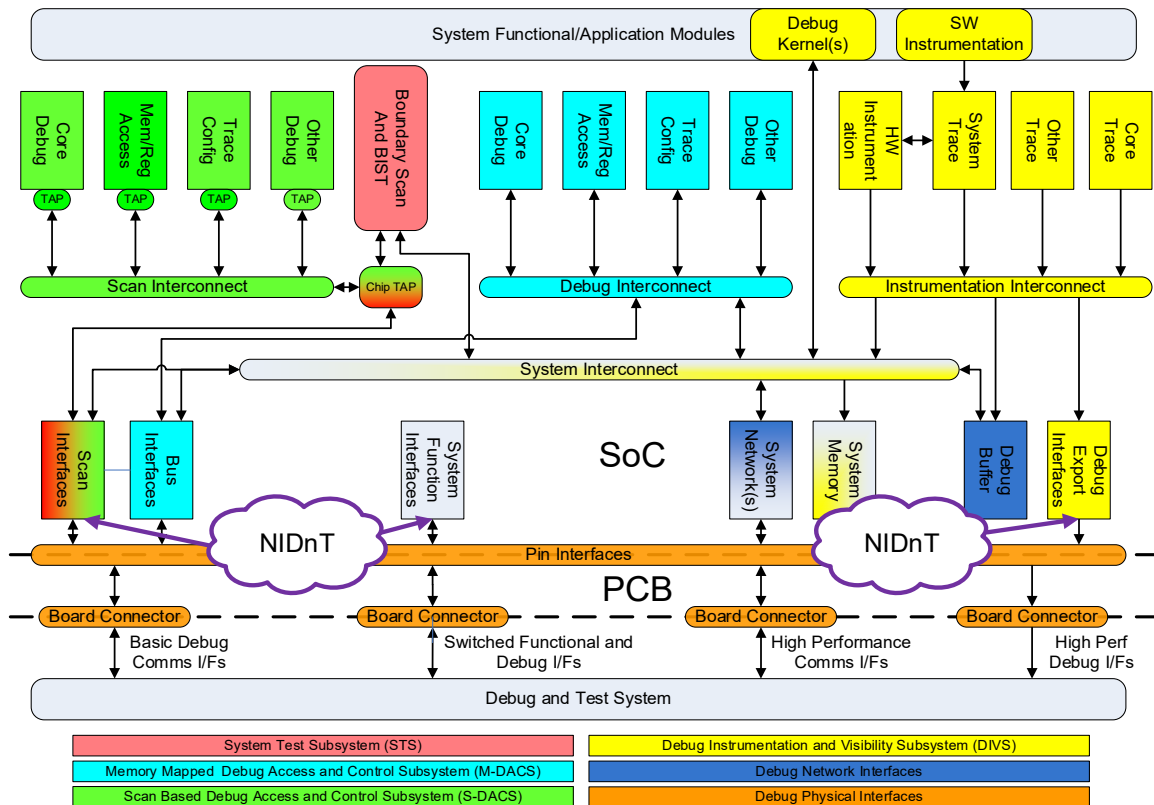
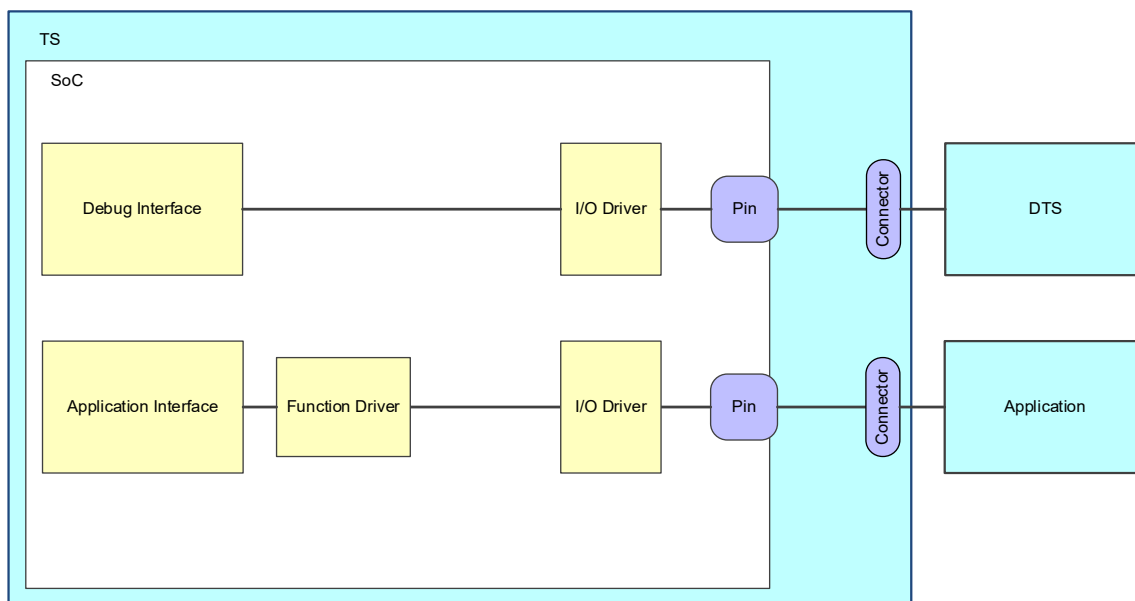


Figure 13 NIDnT in the MIPI Debug Architecture

5.4.3 NIDnT Details

503 NIDnT technology has the potential for changing the product development paradigm as it provides for the
 504 use of one or more of a product's functional interfaces for debug. This can extend the availability of the
 505 debug capabilities used in the early stages of product development to the latter stages. This is especially
 506 valuable when these interfaces are available at the boundary of the product's actual physical enclosure in
 507 the product's final form factor. This change in the product development paradigm is described in the
 508 following paragraphs.

509 During the early stages of product development, IEEE 1149.1/1149.7/SWD/I3C based basic debug, trace of
 510 application activity, and software messages sent over simple streaming interfaces like serial ports are
 511 typically used for debug. Historically, much of this product development is performed using test or
 512 development boards. These boards provide dedicated and readily accessible Debug and Test interfaces for
 513 connecting the tools. A system with a dedicated debug interface is shown in **Figure 14**.

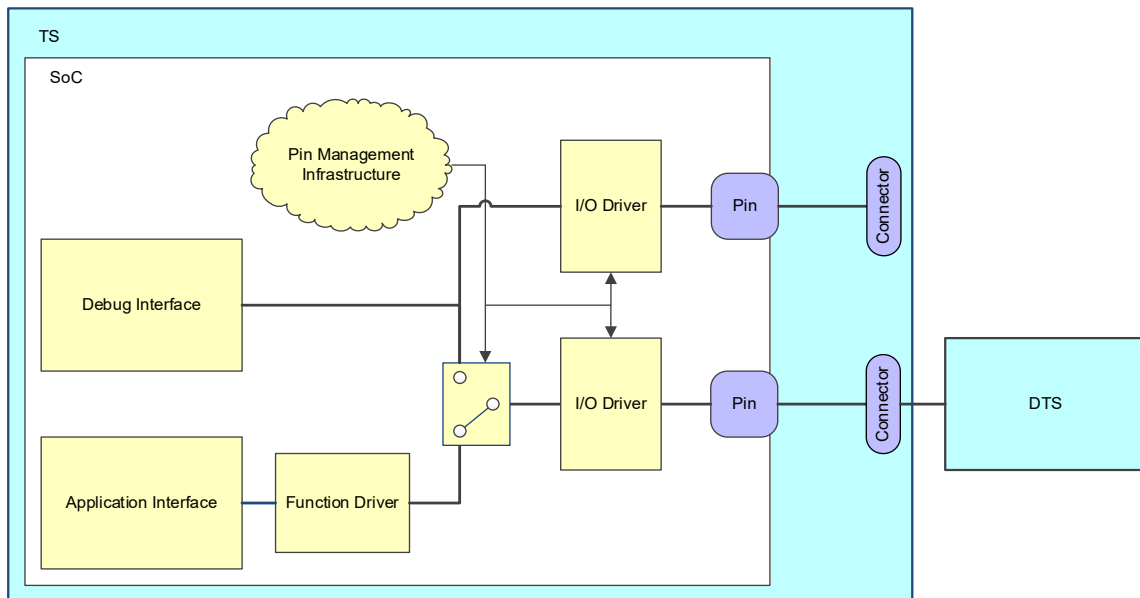


514 **Figure 14 Example of System with a Dedicated Debug Interface**

515 In most cases, a product's final form factor does not have dedicated Debug and Test interfaces as these
 516 interfaces are not propagated to the boundary of the product's physical enclosure. This hampers the
 517 identification of bugs present at this point in the product development.

518 A product might include a proprietary JTAG connector that requires some disassembly (e.g., removing the
 519 battery cover and battery) and the use of a test fixture. The physically invasive process of accessing this
 520 connector could itself cause bugs or RF performance issues to disappear, or new ones to appear.

521 **Figure 15** shows how NIDnT technology extends the use of functional interfaces for Debug and Test
522 purposes. It creates a dual use functional interface by multiplexing the debug signals with the normal
523 function signals within the SoC in a manner that is similar to a switch. Connecting either the normal
524 function or the debug function to the interface connects that function's inputs and outputs to the interface.
525 Disconnecting either the normal function or debug function from the interface connects its inputs to
526 inactive default values that create the function's inert operation while leaving its outputs unused. For
527 example, a SoC could multiplex an IEEE 1149.7 Test Access Port (TAP) and a Parallel Trace Interface
528 (PTI) over the functional I/Os that normally provide a microSD interface. In this case, the IEEE 1149.7
529 TAP could be used for both basic debugging and as a control channel for the trace function that utilizes the
530 PTI interface.



531 **Figure 15 Example of System with NIDnT Capability**

532 It is expected that adapters will be used to connect a product's NIDnT Interface (e.g., microSD interface, or
533 USB) to the MIPI Debug Connectors (as defined in *[MIPI01]*). The use of an adapter provides for
534 debugging the product in its final form factor with standard debug tools, as the adapter remaps the signals
535 presented by the tools on these standard debug connectors to the appropriate positions on the functional
536 connectors.

5.4.4 Debug and Test Capabilities Supported by NIDnT Overlay Modes

537 A NIDnT Interface supports an operating mode that provides all functional operation of the interface
538 (Overlay Mode 0, also called the Original Functional Mode (OFM)) and one or more non-OFM Overlay
539 Modes (Overlay Modes 1 through n) providing debug and test capability.

540 The debug and test capabilities that can be supported with these Overlay Modes are listed below with their
541 associated pin counts shown in parenthesis. These capabilities might be mixed and matched to provide one
542 or more combinations of debug and test capability within the limitations (pin count and drive
543 characteristics) of a specific functional interface or combination of interfaces. The combinations supported
544 for a specific NIDnT Interface are outlined in interface-specific sections of the NIDnT specification.

545

Table 1 Summary of Test/Debug Capabilities Supported by NIDnT

Capability	Interface with Single-Ended Electricals	Interface with Differential Electricals
Basic Debug	<u>2-pin (Min-Pin) Debug</u> <ul style="list-style-type: none"> • IEEE 1149.7 [<i>IEEE02</i>] • Serial Wire Debug [<i>ARM01</i>] • UART • I3C • Vendor Defined Single-Ended Debug 	<u>4-pin High-Speed Debug</u> <ul style="list-style-type: none"> • Vendor Defined Differential Debug
	<u>5-pin Legacy Debug</u> <ul style="list-style-type: none"> • IEEE 1149.1 [<i>IEEE01</i>] 	
	<u>6-pin Modified Legacy Debug</u> <ul style="list-style-type: none"> • Modified IEEE 1149.1 Standard with return clock (deprecated) 	
Trace	<u>Single-Ended Trace</u> <ul style="list-style-type: none"> • Parallel Trace Interface [<i>MIPI02</i>] • Vendor Defined Single-Ended Trace 	<u>High-Speed Trace</u> <ul style="list-style-type: none"> • High-Speed Trace Interface (HTI) [<i>MIPI09</i>] • Vendor Defined Differential Trace
User Defined	Vendor Defined Single-Ended	Vendor Defined Differential

546 The trace function can either run with a clock shared with the 2-pin Min-Pin debug interface or run with an
547 independent clock. If the focus is on maximum trace bandwidth, a shared clock provides the largest number
548 of trace data pins but ties the data rate of each data pin to the clock rate of the 2-pin Min-Pin debug
549 interface.

550 Non-OFM Overlay Modes that support debug, i.e., that switch some of the NIDnT Interface pins to being
551 used for Basic Debug signals, are called Debug Overlay Modes (see table in the NIDnT Specification,
552 [*MIPI05*]).

5.4.5 Functional Interfaces that are NIDnT Candidates

553 The current version of the NIDnT Specification addresses the reuse of the following interfaces:

- 554 • microSD
- 555 • USB (USB 2.0 and USB Type-C™)
- 556 • Display (HDMI and DisplayPort (DP))

557 Future versions of the NIDnT Specification might support other interfaces including, but not limited to:

- 558 • SIM (smart card)
- 559 • UniPro

5.4.6 Detailed Specification

560 For details of NIDnT technology, consult: MIPI Alliance Specification for Narrow Interface for Debug and
561 Test (NIDnT), [*MIPI05*]. This specification is available to MIPI members and to the public through the
562 MIPI website. The public version of the specification can be found at: [http://resources.mipi.org/mipi-nidnt-](http://resources.mipi.org/mipi-nidnt-download)
563 [download](http://resources.mipi.org/mipi-nidnt-download).

6 Debug Access and Control Subsystem (DACS)

6.1 IEEE 1149.7 Debug and Test Interface Specification

564 The IEEE 1149.7 standard [IEEE02] supports the needs of both Debug and Test. It is a superset of the
565 IEEE 1149.1 standard [IEEE01] and represents a natural evolution of this standard. This approach
566 preserves the industry's hardware and software investments in the IEEE 1149.1 standard since its inception.
567 While this is not a MIPI specification, the min-pin debug effort started in MIPI, so it is included here to
568 help complete the debug framework. The standard:

- 569 • Provides a substantial, yet scalable set of additional debug related capability
- 570 • Supports multiple connection topologies
 - 571 • Four-wire series or star
 - 572 • Two-wire star
 - 573 • Halves the width of the interface in two-wire star configurations while maintaining performance

574 Six capability classes (T0-T5) are supported, with the implementer selecting the capability class
575 implemented. A class defines both mandatory and optional capability. Class capability increases
576 progressively, with the capability of a class including the capability of all lower numbered classes.

577 Capability classes T0-T2 support operation with the four-wire Test Access Port (TAP) (defined by the IEEE
578 1149.1 standard) connected in a four-wire series topology. Each of these classes incrementally extends the
579 IEEE 1149.1 capability while using only the Standard Protocol defined by the IEEE 1149.1 standard.

580 Capability classes T3 additionally supports deployment in a four-wire star topology.

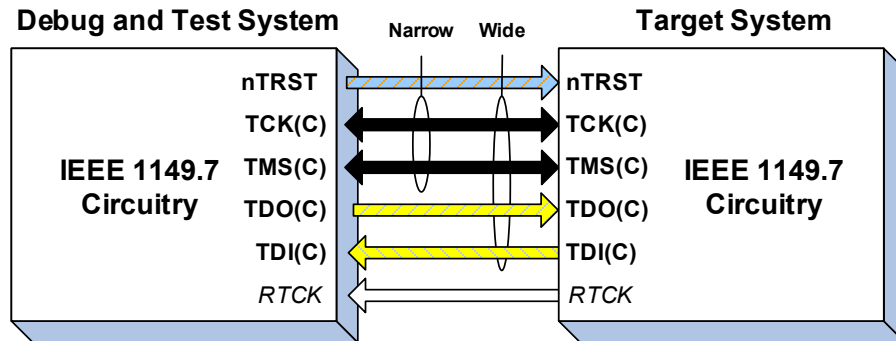
581 Capability classes T4-T5 provide for implementing devices with either a four-wire TAP (IEEE 1149.1 style)
582 or a two-wire TAP (unique IEEE 1149.7 style). Devices with the four-wire TAP configuration can be
583 operated in all connection topologies. Devices with the two-wire TAP configuration can be operated only in
584 a two-wire scan topology.

585 The T4-T5 classes incorporate the Advanced Protocol. The Advanced Protocol provides for the joint use of
586 the TAP for real-time system instrumentation, classic debug, and test, using only the TCKC and TMSK
587 signals as it:

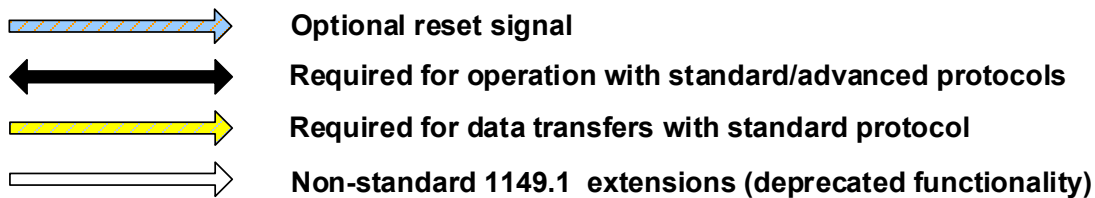
- 588 • Redefines the functionality of the IEEE 1149.1 TCKC and TMSK signals
- 589 • Eliminates the need for the TDIC and TDOC signals
- 590 • Allows the use of the TAP for both scan and non-scan data transfers

591 The combination of a two-wire TAP and use of the Advanced Protocol provides the capability of a five-
592 wire IEEE 1149.1 TAP using only two signals, plus additional system debug capability.

593 A high-level view of the IEEE 1149.7 interface connectivity between a DTS and TAPs within the TS is
 594 shown in **Figure 16**. Both the four-wire (wide) and two-wire (narrow) TAP configurations are shown with
 595 an optional test reset signal. A deprecated non-standard return clock signal is also comprehended with the
 596 four-wire configuration (the use of this and other non-standard signals is strongly discouraged by the
 597 standard).



Although TCKC is shown as bidirectional it is sourced by either the DTS or the TS



598

Figure 16 DTS to TS Connectivity

599 All capability classes begin operation using the Standard Protocol. IEEE 1149.7 operation is compatible
 600 with IEEE 1149.1 from power-up, with the function of TCK(C) and TMS(C) signals providing the
 601 functionality (or a superset thereof) of the TCK and TMS signals that is specified by the IEEE 1149.1
 602 standard.

603 All IEEE 1149.7 based devices may be implemented in a manner that allows their use in system
 604 configurations where there is:

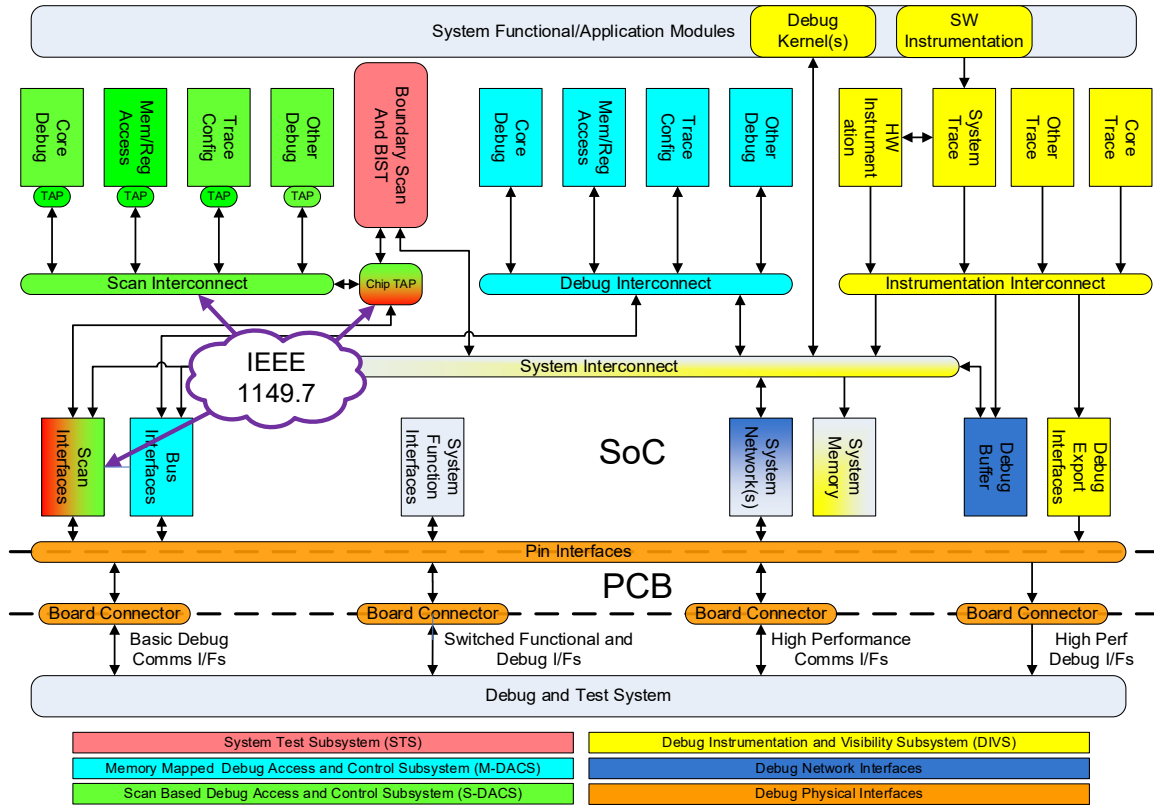
- 605 • A mix of components implementing different capability classes
- 606 • A mix of connection topologies

607 The DTS can use facilities defined by the standard to determine the following:

- 608 • The types of connection topologies deployed within the TS
- 609 • The component mix with the TS:
 - 610 • 1149.1 components
 - 611 • 1149.7 components + class of each component

6.1.1 Relationship to MIPI Debug Architecture

612 **Figure 17** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
613 IEEE 1149.7 standard.



614 **Figure 17 IEEE 1149.7 in the MIPI Debug Architecture**

6.1.2 Detailed Specification

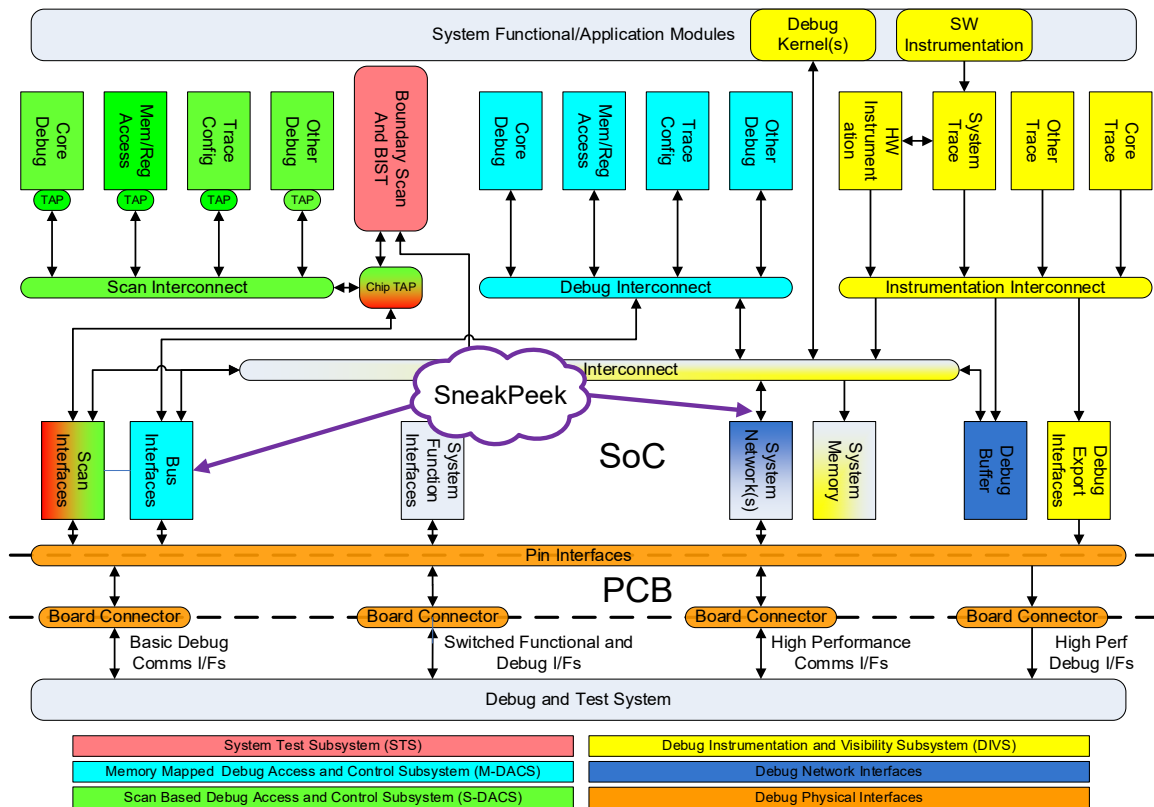
615 For details of the 1149.7 specification, consult the document: IEEE 1149.7 Standard for Reduced-pin and
616 Enhanced-functionality Test Access Port and Boundary Scan Architecture **[IEEE02]**.

6.2 SneakPeek Specification

617 The SneakPeek framework is intended to enable debugging of a Target System via standard network
 618 connection. This is accomplished by moving a portion of the Debug and Test Controller function onto the
 619 SoC. These embedded DTC functions can be reached by network communication links that previously have
 620 not been leveraged for *DTC-like* debug. SneakPeek also leverages a significant portion of the on-chip
 621 debug infrastructure. As a result, DTC tools that previously used dedicated debug links (e.g., 1149.7 or PTI)
 622 can easily be ported to work in a SneakPeek framework through simple network adaptor layers. The
 623 identical capabilities realized via the dedicated debug interfaces should be available via SneakPeek (with
 624 possible performance penalties).

6.2.1 Relationship to MIPI Debug Architecture

625 **Figure 18** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
 626 SneakPeek specification.



627 **Figure 18 SneakPeek in the MIPI Debug Architecture**

6.2.2 Overview

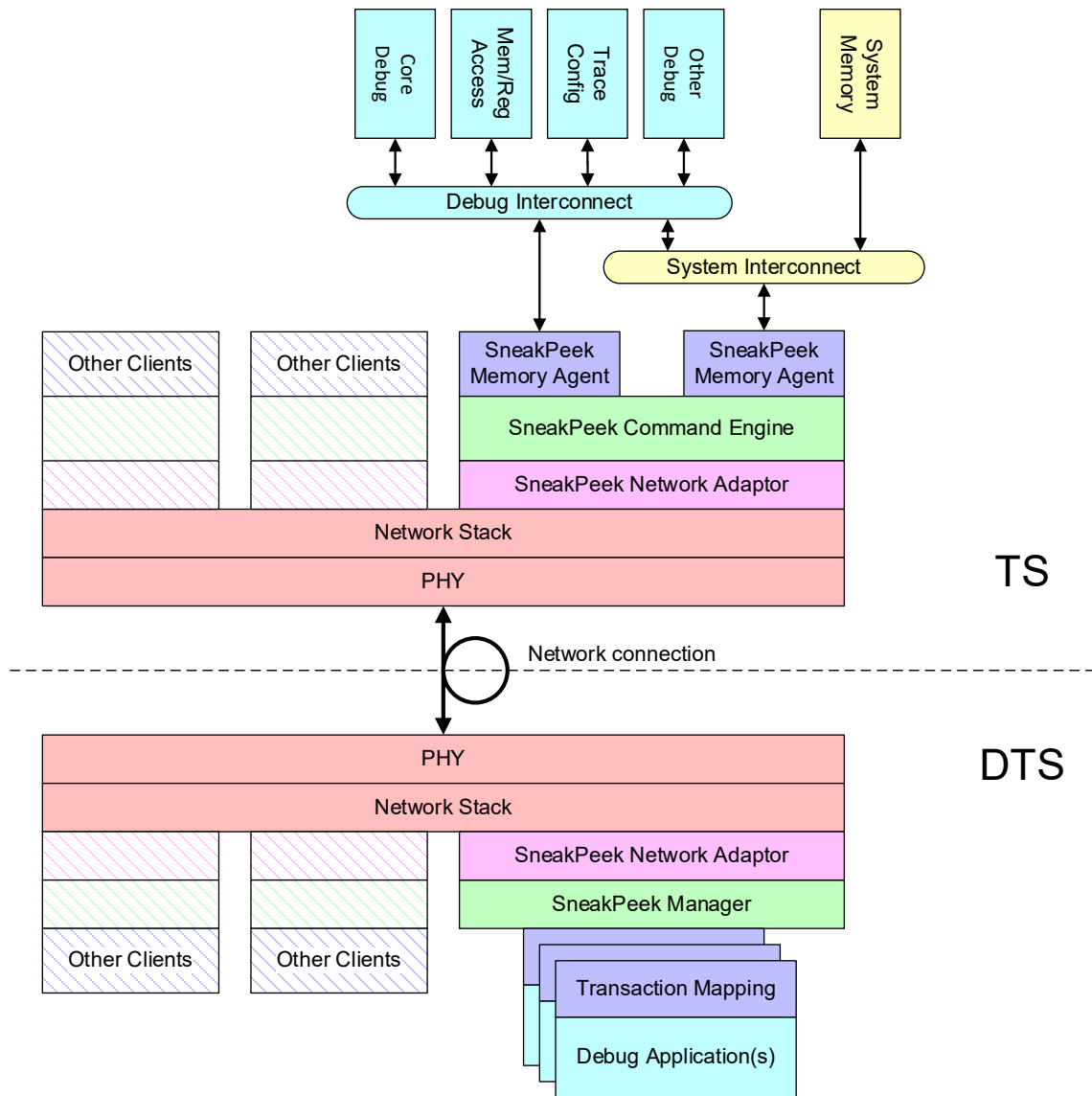
628 The SneakPeek Protocol (SPP) is used to communicate between a Debug Test System (DTS) and a Target
 629 System (TS). This communication facilitates using Debug Applications (typically software) within the DTS
 630 to debug the operation of the TS.

631 The SneakPeek Protocol abstracts the system designer from dedicated debug communication interfaces
 632 such as JTAG and replaces them with the familiar mechanism of address-mapped read and write
 633 transactions to enable the Debug Applications to observe, interrogate and adjust the Target System. These

634 transactions might be addressed to main system memory, special function memories, or address-mapped
635 peripherals within the TS.

636 If the system requires legacy dedicated debug communication interfaces to be used internally within part of
637 a system, then these could be constructed by a dedicated address-mapped peripheral within the Target
638 System that is then accessed by the DTS via SneakPeek.

639 **Figure 19** illustrates the route by which one or more debug software applications in a DTS utilize
640 SneakPeek Memory Agents within a TS to perform address-mapped transactions for them.



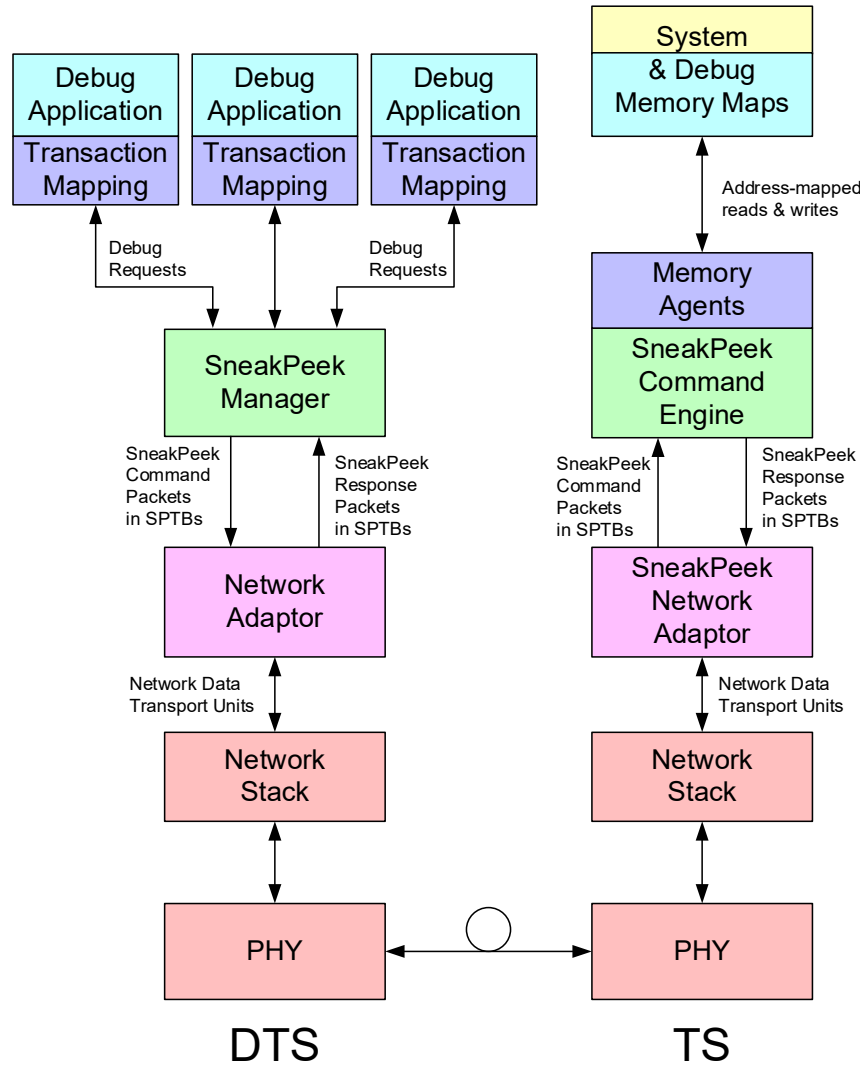
641

Figure 19 Overview of SneakPeek System

642 The basic communication units used by SneakPeek are SneakPeek Command Packets sent from the DTS to
643 the TS, and SneakPeek Response Packets sent from the TS to the DTS. To provide more efficient
644 interactions with the communication network, the DTS packs typically many Command Packets into a
645 single SneakPeek Transfer Block (SPTB) before handing this over to the network driver for transmission to

646 the TS. Similarly, the TS packs typically many Response Packets into a single SPTB for transmission to the
647 DTS.

648 **Figure 20** shows how the SneakPeek Protocol is built on top of existing network infrastructure.



649

Figure 20 SneakPeek Protocol and Network Stacks in DTS and TS

650 In summary:

- 651 • The DTS sends SneakPeek Command Packets grouped into SPTBs to the TS over a data
652 communication network.
- 653 • These Command Packets cause an action or effect in the TS, typically an address-mapped read or
654 write transaction. The Command Engine generates a Response Packet corresponding to each
655 Command Packet (with some special case exceptions).
- 656 • The TS sends SneakPeek Response Packets grouped into SPTBs to the DTS over the data
657 communication network.
- 658 • The SneakPeek Packets in a stream have a defined order at their source and are interpreted in this
659 order at their destination. The SneakPeek Protocol is not concerned with actual transmission order

660 over the physical or other layers of the network stack but assumes that the network reconstructs
661 the original order before handing off the SneakPeek Packets at their destination.

6.2.3 Protocol Styles

662 SPP version 2.0 introduces TinySPP, an “optimized” style of the SneakPeek Protocol focusing on low
663 bandwidth interfaces and “tiny” implementations. TinySPP provides a reduced feature-set (e.g., no
664 sequence number, reduced access space, reduced direct addressing space, and no access size variability)
665 and “coexists” with SPP version 1.0, or FullSPP. Reducing the size of the Command and Response Packets
666 is done by assuming certain behaviors and by placing some restrictions on these interfaces. These
667 restrictions and assumptions are usually acceptable as a tradeoff for a smaller and simpler implementation
668 more tailored for lower bandwidth and/or half-duplex interfaces.

669 The main differences between the TinySPP and FullSPP styles are shown in *Table 2*.

Table 2 Comparison of SneakPeek Protocol Styles

Feature	TinySPP	FullSPP
Number of Access Spaces	8 (3-bit field)	32 (5-bit field)
Sequence Number	N/A. Additional requirements to network: <ul style="list-style-type: none"> • Messages stay in order • Guaranteed Delivery • DTS/TS has to do book-keeping for request/response 	Present
Standard Size Field	Chosen by TS	Different options
Size of Transaction Byte Count (TBC) Field	7 bits	16 bits
Short Addressing	6-bit address replacement supported. Short addressing is required in a TinySPP implementation	N/A
Packet Alignment	Byte aligned	16-Byte aligned
Shortest Packet Length	4 Bytes	16 Bytes
Usage in MIPI Specifications	Debug for I3C	GbD for USB, GbD for IPS

6.2.4 Detailed Specifications

670 For details of the SneakPeek Protocol, consult the document: MIPI Alliance Specification for SneakPeek
671 Protocol, *[MIP106]*. This specification is available to MIPI members and to the public through the MIPI
672 website. The public version of the specification can be found at: [http://resources.mipi.org/mipi-spp-v2-](http://resources.mipi.org/mipi-spp-v2-download)
673 [download](http://resources.mipi.org/mipi-spp-v2-download).

This page intentionally left blank.

7 Debug Instrumentation and Visibility Subsystem (DIVS)

7.1 Instrumentation and Visibility Subsystem Overview

674 The DIVS is basically a network or interconnect that allows trace data to flow from various sources to the
675 trace data sink (generally the DTS). The DIVS architecture provides a rich set of features that can be
676 utilized to effect this purpose:

- 677 • Trace protocols such as the System Trace Protocol (STP) that provide a standard encoding for
678 trace from multiple different HW and SW sources.
- 679 • Trace merge protocols such as the Trace Wrapper Protocol (TWP) that can be used to combine
680 many different trace streams into a single stream of data for easy transport management.
- 681 • Trace network protocols like the Gigabit Trace (GbT) and network adaptor specifications that
682 define how trace data should be formatted for transport over standard network links.

7.2 System Trace Protocol (STP) Specification

683 Real-time trace has become an indispensable tool for debugging and optimizing embedded systems. This
684 trace can come from a variety of sources, including:

- 685 • Trace components monitoring processor instruction and data flow.
- 686 • Instrumentation in the software running on a processor.
- 687 • Trace components monitoring activities outside the processor.

688 Each trace source has its own protocol, and these protocols share a number of common required features.
689 The System Trace Protocol (STP) is a base protocol which provides these common features.

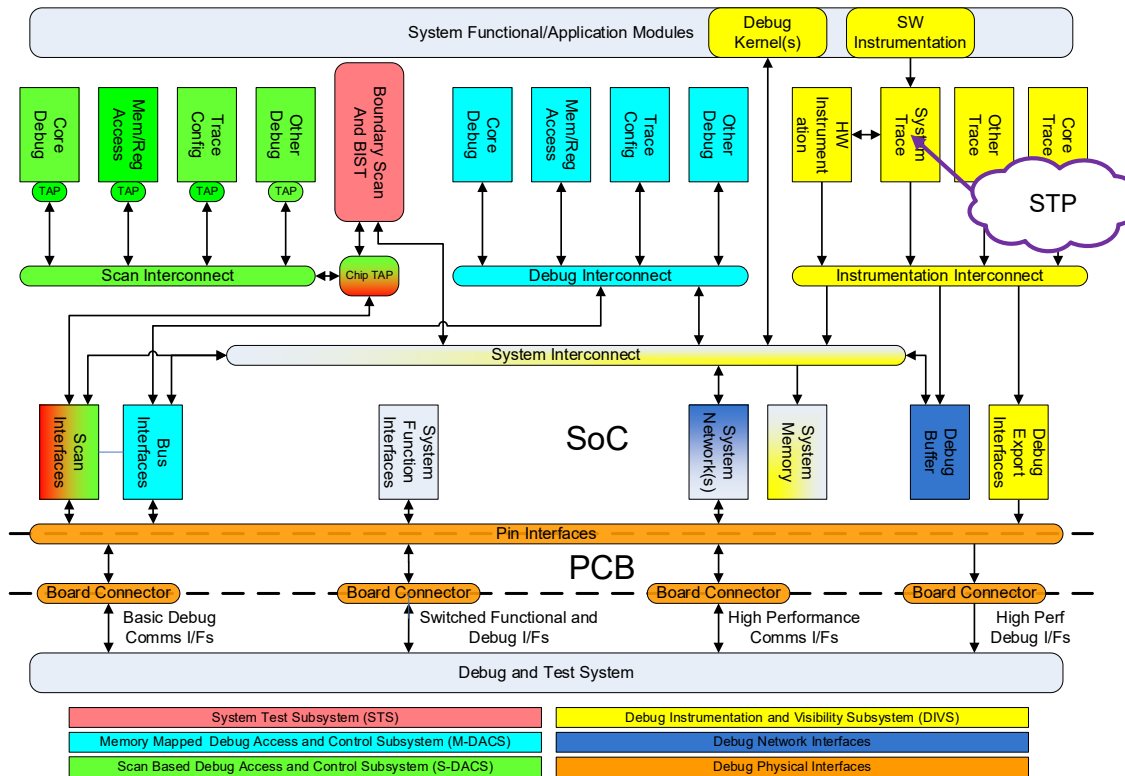
690 The advantages of this shared approach are:

- 691 • Reuse reduces the time and cost of designing new protocols, as well as IP and tools supporting
692 them.
- 693 • Commonality of features enables greater interoperability, for example by providing time
694 correlation between multiple trace streams.
- 695 • A robust base protocol ensures common protocol design mistakes are avoided.

696 The STP specifications were developed to leverage the advantages listed above. STP was not intended to
697 supplant or replace the highly optimized protocols used to convey data about processor program flow,
698 timing or low-level bus transactions. It is anticipated that STP data streams will exist side by side with
699 these optimized protocols as part of a complete debug system.

7.2.1 Relationship to MIPI Debug Architecture

700 **Figure 21** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
701 STP specifications.



702 **Figure 21 STP in the MIPI Debug Architecture**

7.2.2 Protocol Overview

703 STP was developed as a generic base protocol that can be shared by multiple, application-specific trace
704 protocols. STP was not intended to supplant or replace the highly optimized protocols used to convey data
705 about processor program flow, timing or low-level bus transactions. STP is designed so that its data streams
706 coexist with these optimized protocols as part of a complete debug system. The STP protocol is now in its
707 second generation (STPv2) which is backward compatible with the first generation.

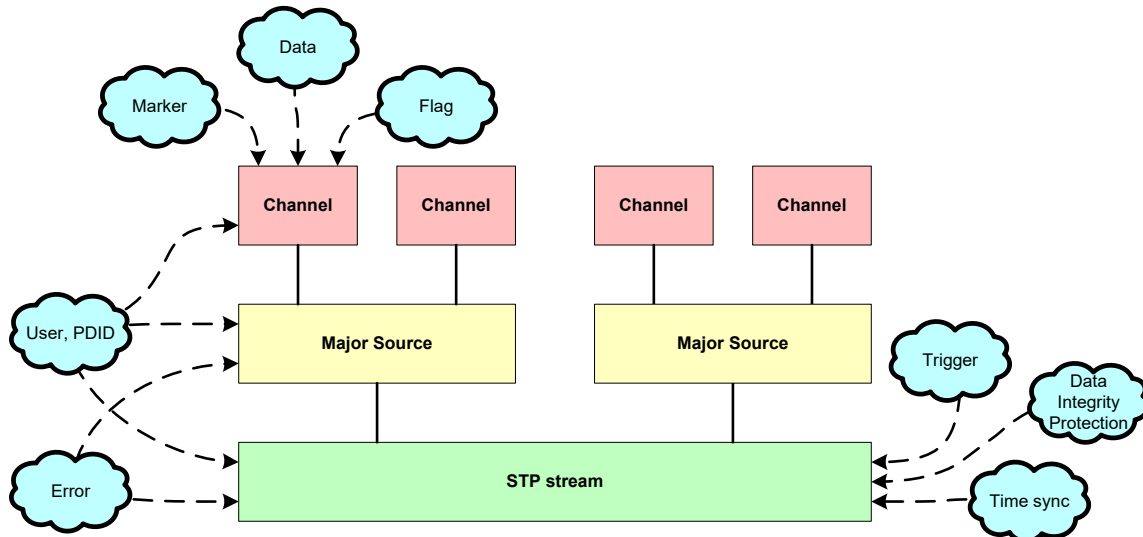
708 STPv2 includes the following features:

- 709 • A trace stream comprised of 4-bit frames (nibbles)
- 710 • Support for merging trace data from up to 65536 independent data sources
- 711 • Up to 65536 independent data Channels per Major Source
- 712 • Basic trace data messages that can convey 4, 8, 16, 32, or 64-bit wide data
- 713 • Time-stamped data packets using one of several time stamp formats including:
 - 714 • Gray code
 - 715 • Natural binary
 - 716 • Natural binary delta
 - 717 • Export buffer depth (legacy STPv1 timestamp that requires DTC support)
- 718 • Data packet markers to indicate packet usage by higher-level protocols
- 719 • Flag packets for marking points of interest (for higher-level protocols) in the stream

- 720 • Packets for aligning time stamps from different clock domains
- 721 • Packets for indicating to the DTC the position of a trigger event, which is typically used to control
- 722 actions in the DTC; for example, to control trace capture
- 723 • Packets for cross-synchronization events across multiple STP sources
- 724 • Support for user-defined data packets
- 725 • Facilities for synchronizing the trace stream on bit and message boundaries
- 726 • Optional support for data integrity protection of the trace stream
- 727 • Add data integrity package (DIP) to facilitate error detection over noisy connections
- 728 • Platform Description ID (PDID) packet types to carry payload information identifying the
- 729 platform the trace was captured and describe the contained trace data formats to enable processing
- 730 tools to auto-detect the format of the individual traces received from the trace stream itself.

731 **Figure 22** shows the conceptual hierarchy of the different terms described in this specification. The clouds
732 are elements from the data model.

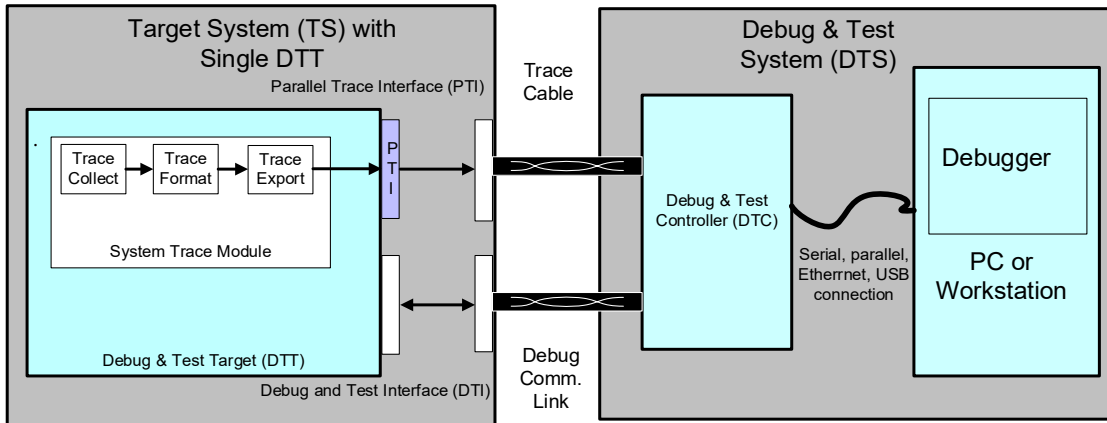
733 A stream of STP packets generally contains data from a number of different Major Sources, which in turn
734 may each have a number of different Channels. These two levels of hierarchy may be used, for example, to
735 distinguish different software applications (Channels) running on different processors (Major Sources).



736

Figure 22 Conceptual Hierarchy of STP Major Sources and Channels

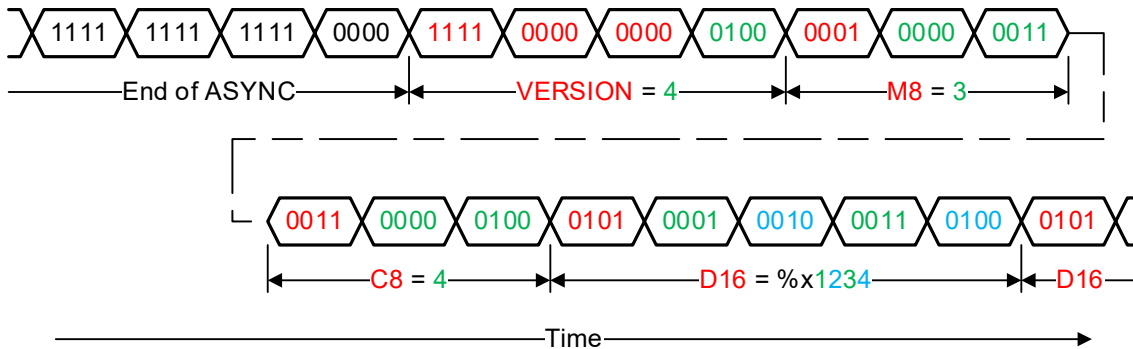
737 **Figure 23** shows an example of a target system that utilizes a module implementing the System Trace
738 Protocol. In this example, the STP data is transferred to the DTC across a PTI.



739

Figure 23 STM in a Target System

740 The timing diagram in *Figure 24* shows an example of the STP packets that might be transferred to the
 741 DTC in such a system. This example shows the end of a synchronization sequence followed by a series of
 742 16-bit data packets on Channel 4 of Trace Source (Major Source) 3.



743

Figure 24 Example STP Packet Sequence

7.2.3 Detailed Specification

744 In addition to the current version 2.2 of the MIPI STP Specification, version 2.3 is under development in
 745 the MIPI Debug Working Group and is expected to be available in 2021. Version 2.3 will add a new
 746 Platform Description ID packet for identifying the correct decoder(s).

747 For details of MIPI STP, consult the document: MIPI Alliance Standard for System Trace Protocol
 748 Specification Version 2.2, [*MIPI03*]. This specification is available to MIPI members and to the public
 749 through the MIPI website. The public version of the specification can be found at:
 750 <http://resources.mipi.org/mipi-download-system-trace-protocol>.

7.3 Trace Wrapper Protocol (TWP) Specification

7.3.1 Overview

751 The Trace Wrapper Protocol (TWP) enables multiple source trace streams to be combined (merged) into a
752 single trace stream. The basic principle is that the source trace streams (byte streams) can be assigned
753 system unique IDs. A wrapping protocol is then used to encapsulate all the streams in the system
754 identifying them with these IDs. This protocol also includes provisions for synchronizing the merged
755 output stream and providing inert packets for systems that cannot disable continuous export of data. It has
756 optional facilities for indicating to the Debug and Test Controller (DTC) the position of a trigger event,
757 which is typically used to control actions in the DTC, for example to control trace capture.

758 This specification is complementary to the MIPI Alliance Specification for Parallel Trace Interface (PTI),
759 *[MIPI02]*, and to the MIPI Gigabit Debug network adaptor specifications, such as *[MIPI07]*. It is intended
760 to be used by any module or layer that merges multiple trace data streams. The ultimate destination of the
761 merged streams might include:

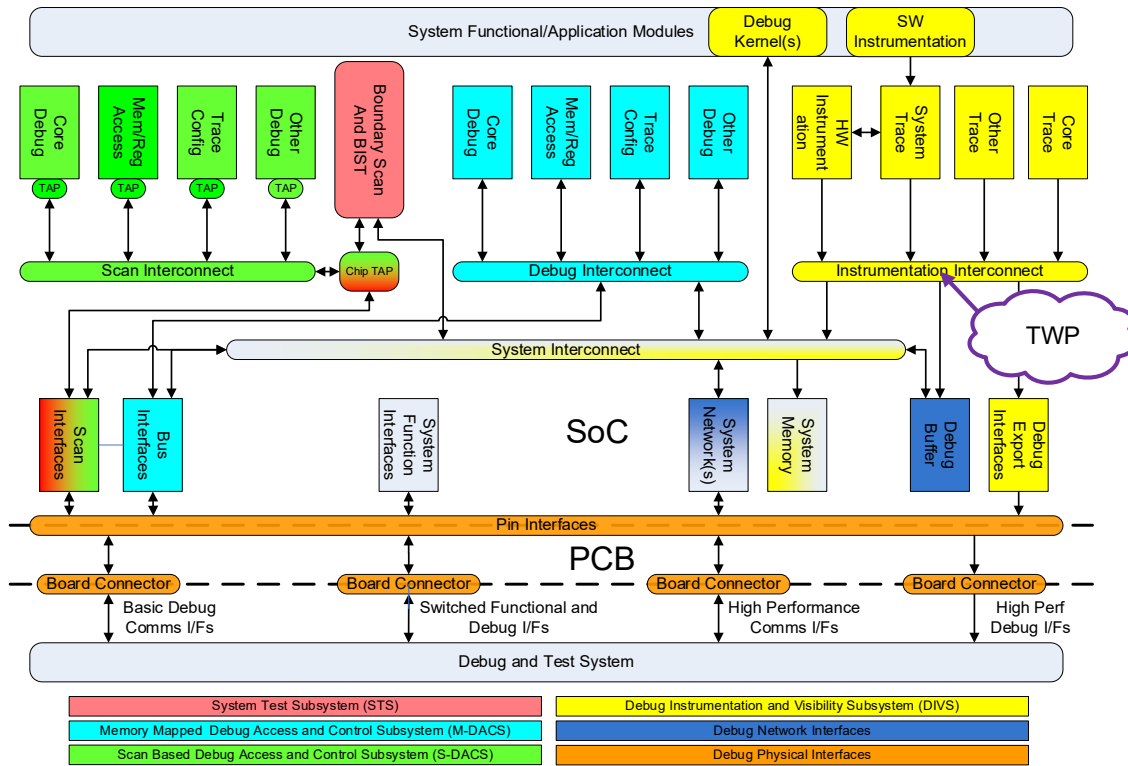
- 762 • Host debug tools via a dedicated trace export interface (PTI)
- 763 • On-chip capture into a dedicated trace buffer
- 764 • On-chip capture into general system memory
- 765 • Host debug tools via a functional network (GbD)

766 This specification is also complementary to the MIPI Alliance Specification for System Trace Protocol,
767 *[MIPI03]*, enabling a trace output to be shared between sources that implement STP and logic that
768 implements other trace protocols.

769 This specification is equivalent to the Trace Formatter Protocol specified in the Arm® CoreSight™
770 Architecture Specification, *[ARM01]*.

7.3.2 Relationship to MIPI Debug Architecture

771 **Figure 25** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
772 TWP specification.



773 **Figure 25 TWP in the MIPI Debug Architecture**

7.3.3 TWP Features

774 The features of TWP are summarized below:

- 775 • Allows up to 111 source trace streams to be represented as a single stream and later separated by
776 either hardware or software.
- 777 • Requires low additional bandwidth.
- 778 • Minimizes the amount of on-chip storage required to generate the protocol.
- 779 • Permits any source trace stream to be used, regardless of its data format.
- 780 • Is suitable for high-speed real-time separation of the component trace streams.
- 781 • Is a bit stream that can be exported using any transport that supports bit stream data.
- 782 • Can be efficiently stored to memory whose width is a power of two for later retrieval.
- 783 • Has facilities for synchronization points so decode can be accomplished even if the start of the
784 trace is lost.
- 785 • Has facilities for indicating to the Debug and Test Controller (DTC) the position of a trigger event,
786 which is typically used to control actions in the DTC, for example to control trace data capture.
- 787 • Has facilities for padding the data output for scenarios where a transport interface cannot be idled,
788 and valid data is not available.

7.3.4 TWP Description

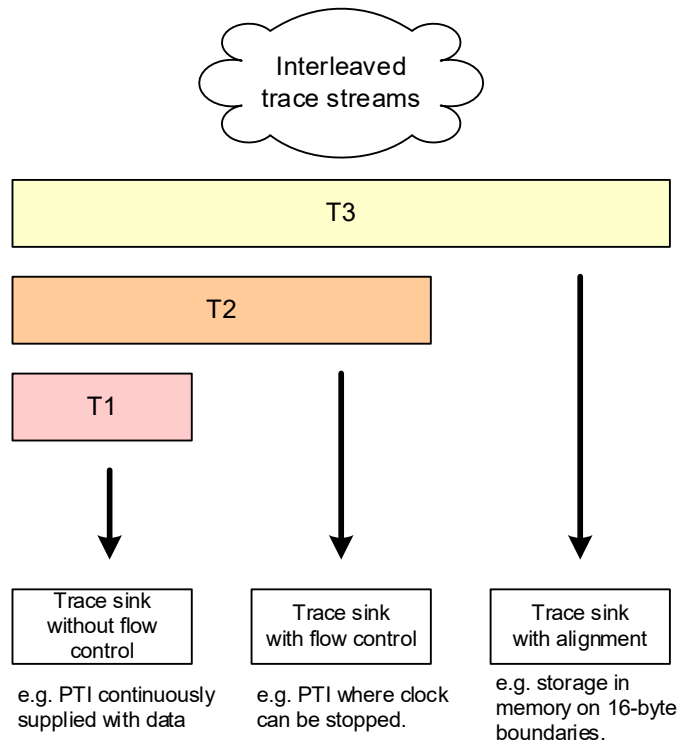
789 Each trace source, whose output is to be wrapped by TWP, is given a 7-bit trace source ID. The trace
790 consists of a number of Trace Fragments, each consisting of an ID indicating the source of the trace and at
791 least one byte of data.

792 If the source trace stream cannot be naturally represented using a stream of bytes, then an additional
793 protocol specific to the source trace stream has to be implemented in order to convert the source trace
794 stream into a stream of bytes.

7.3.5 Layers

795 TWP is split into the following layers:

- 796 • Layer T1: Flow Control. This layer enables TWP to be used over a connection which requires
797 continuous communication, for example PTI in situations where the clock cannot be stopped.
- 798 • Layer T2: Alignment Synchronization. This layer enables the alignment of frames in Layer T3 to
799 be determined.
- 800 • Layer T3: Data. This layer conveys trace data using 128-bit frames.



801

Figure 26 Example Use Cases for Layers T1, T2 and T3

7.3.6 Detailed Specification

802 For details of MIPI TWP, consult the document: MIPI Alliance Specification for Trace Wrapper Protocol,
803 *[MIPI04]* and *[MIPI04a]*. This specification is available to MIPI members and to the public through the
804 MIPI website. The public version of the specification can be found at: [http://resources.mipi.org/mipi-twp-](http://resources.mipi.org/mipi-twp-download)
805 [download](http://resources.mipi.org/mipi-twp-download).

7.4 Gigabit Trace (GbT)

7.4.1 Summary

806 One of the primary functions of the DIVS is to provide means to organize on-chip data and transport it to
 807 an external Debug and Test System for analysis. Historically, this data path used dedicated interfaces on the
 808 SoC boundary (the Parallel Trace Interfaces introduced earlier). In some system scenarios, however, it is
 809 desirable to transport the trace data via networks and interfaces which are shared with traffic sent by the
 810 mission mode (normal) functions of the device. Leveraging functional interfaces and transports for debug
 811 enhances the capabilities of the debug systems in scenarios where debug over dedicated interfaces is
 812 difficult or impossible. Gigabit Trace (GbT) focuses on the sharing of standard communication channels for
 813 debug.

814 The GbT architecture is a layered system. The GbT System facilitates packaging trace data as a stream of
 815 GbT Network messages suitable for transport over a shared network and/or interconnect. It defines a
 816 network independent set of data packets that are shared (but not required) by all network transports.

817 A Gigabit Trace system also requires a Network Adaptor that consumes GbT Network Messages and
 818 produces a message stream compatible with the targeted transport. The network adaptor layers are generally
 819 called Gigabit Debug Adaptors since they often support other network capable debug protocols like
 820 SneakPeek. The goal is to define MIPI Gigabit Debug network adaptor specifications for all the common
 821 transports found in different systems.

7.4.2 Relationship to MIPI Debug Architecture

822 **Figure 27** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
 823 Gigabit Trace specifications.

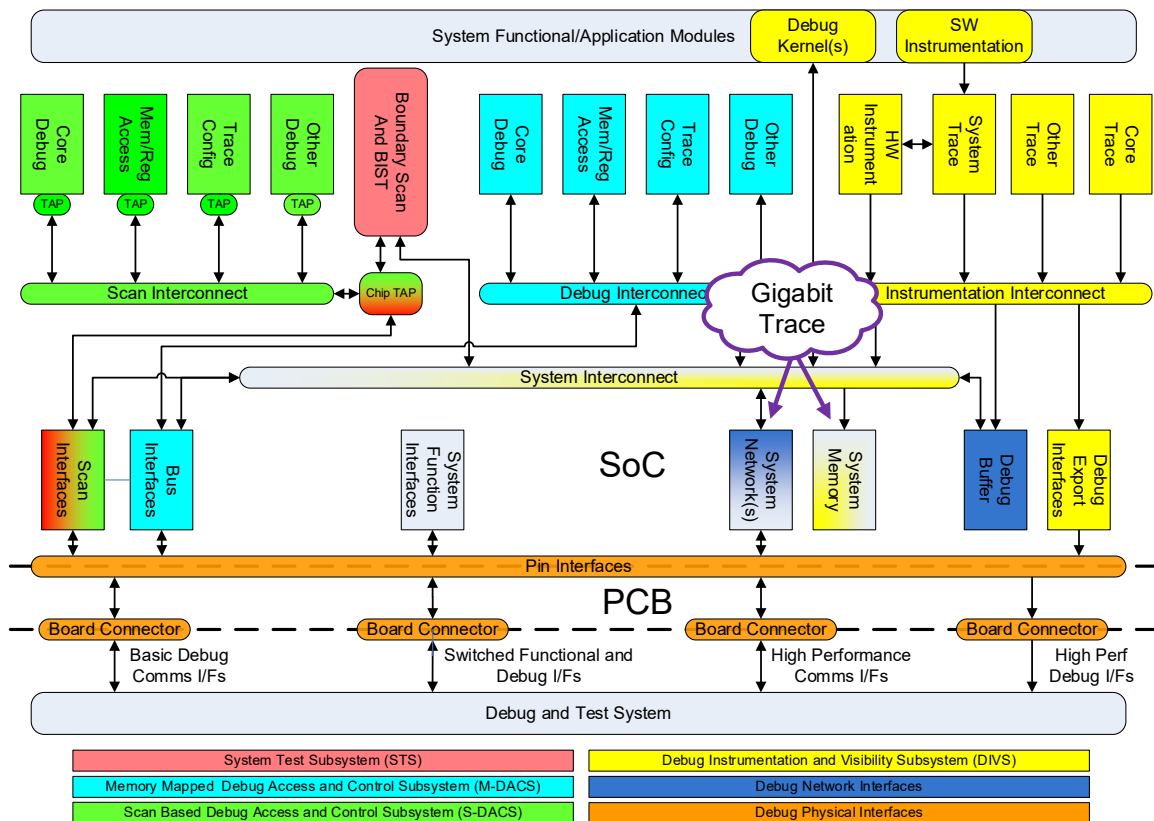
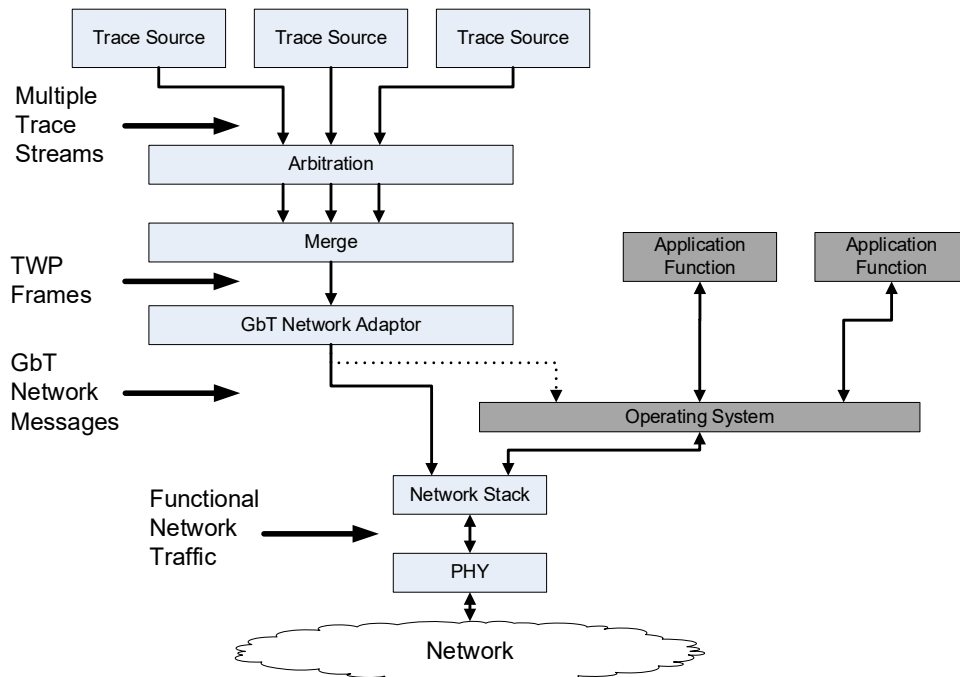


Figure 27 Gigabit Trace and the MIPI Debug Architecture

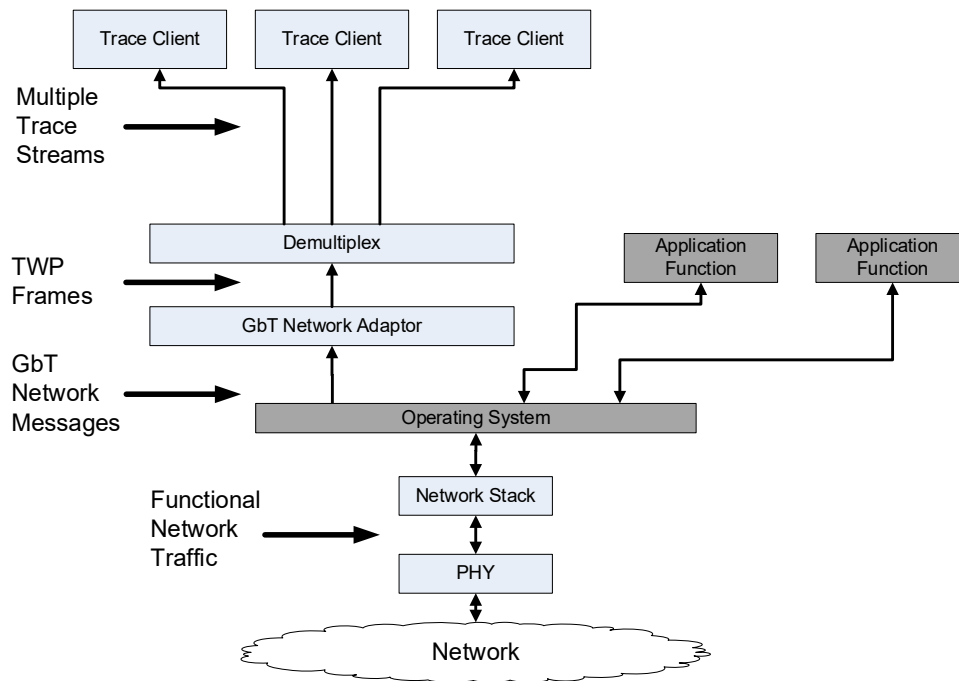
7.4.3 Gigabit Trace System Overview

825 The TWP has facilities to readily adapt trace streams for export over the high-speed network interfaces
826 present on different systems. As these functional interfaces are now supporting extremely high data rates,
827 the term Gigabit Trace (GbT) has been coined. In a GbT system, the trace stream can co-exist on the
828 network link with other (functional) data traffic and the debug tooling is an application layer client on the
829 network. This approach enables trace capture in fielded systems where dedicated debug connections are not
830 available. It also enables trace capture in the DTS using any host system (such as a high-performance PC)
831 that supports a high-speed network interface and can store data at high data rates.

832 **Figure 28** and **Figure 29** show a typical GbT system and the data flow in the TS and the DTS. These
833 figures are abstract functional diagrams that illustrate data flow through the system. The individual blocks
834 only define functions that likely exist in the system, not HW or SW modules with defined interfaces and
835 behaviors.



836 **Figure 28 Typical GbT Configuration and Data Flow (TS)**



837

Figure 29 Typical GbT Configuration and Data Flow (DTC and DTS)

838 Note that in the TS, the GbT data path may optionally use the low-level OS to merge trace data with other
 839 (functional) network streams. This is obviously more intrusive to the system function than a direct data path
 840 to the lower levels of the network stack (also shown). A more SW-intensive system might ease the
 841 complexity of the HW required to support GbT and it is anticipated that both approaches will be utilized.

842 The MIPI GbT solution builds on the MIPI TWP data primitives. The MIPI GbT solution uses a GbT
 843 Network Adaptor (in the TS and DTS) to isolate generic GbT from the properties of a specific Network
 844 Stack. A typical GbT system might adapt trace for export over a USB interface (USB 2.0 or 3.0 depending
 845 on bandwidth requirements).

846 The MIPI Debug Working Group will produce independent specifications defining how a GbT system can
 847 be realized on various transport networks. These *Adaptor* specifications will provide the details on how to
 848 map the GbT framework outlined in this Annex to specific constraints and capabilities of a particular
 849 transport network.

7.4.4 Requirements Summary

850 A GbT system generally addresses the following requirements:

- 851 • Provides a mechanism to convey high bandwidth trace data over a transport network.
- 852 • Compatible with a variety of transport networks.
- 853 • Packages trace data streams into network-independent messages.
- 854 • Builds on existing network protocol specifications (referred to as the functional or transport
 855 network).

7.4.5 Detailed Specification

856 The details of the Gigabit Trace framework are outlined in an annex to the MIPI Alliance Specification for
 857 Trace Wrapper Protocol, version 1.1.

858 For details of the Gigabit Trace framework, consult the document: MIPI Alliance Specification for Trace
 859 Wrapper Protocol, [MIPI04a]. This specification is available to MIPI members and to the public through

860 the MIPI website. The public version of the specification can be found at: <http://resources.mipi.org/mipi->
861 [twp-download](http://resources.mipi.org/mipi-twp-download).

7.5 STP and TWP in the DIVS

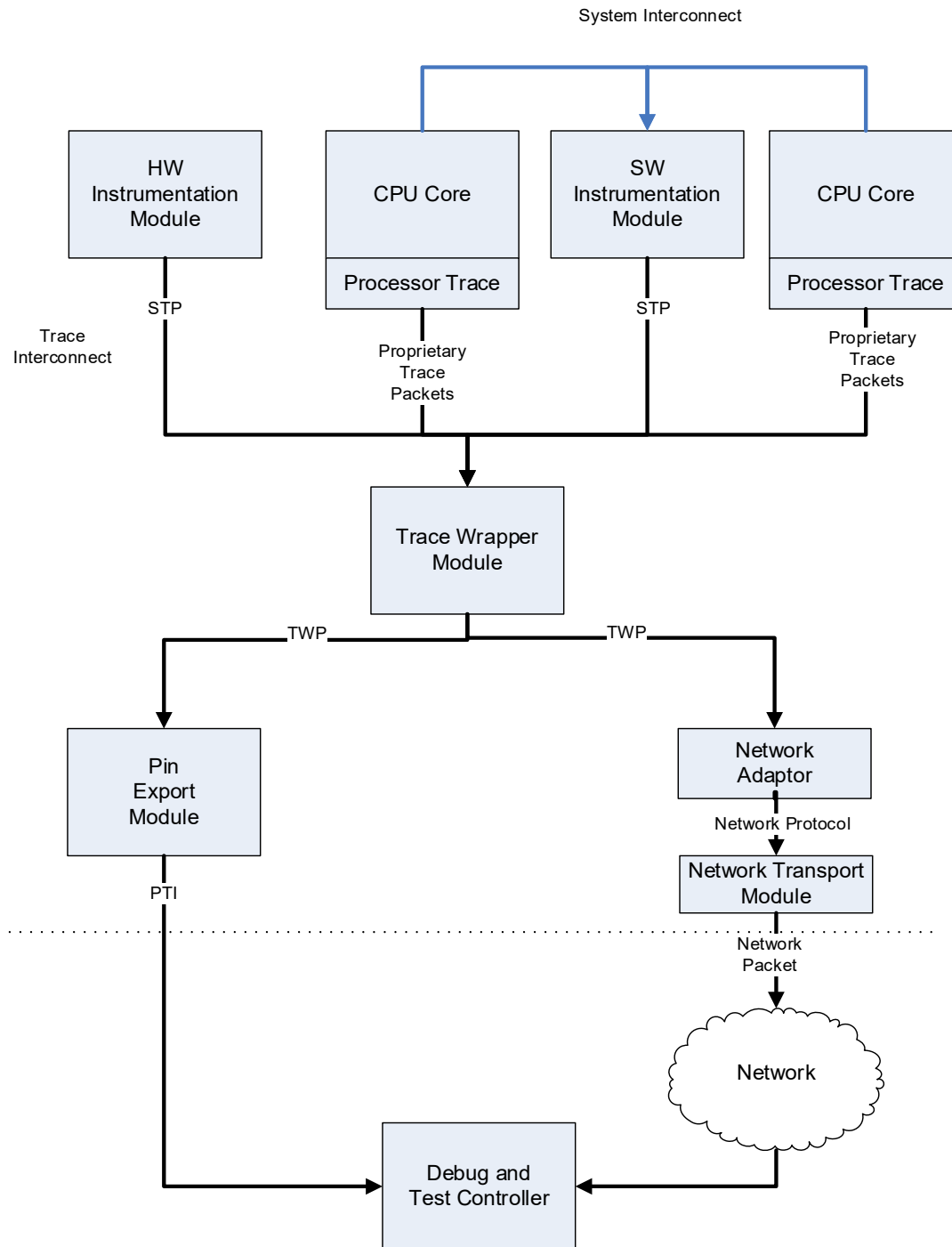
862 At first inspection, it might seem that STP and TWP have significant functional overlap. Both support the
863 merging of trace data from multiple trace sources. They also have facilities for stream synchronization and
864 alignment. A more detailed analysis, however, reveals that the protocols are optimized for different
865 capabilities and the differences in the protocols complement each other in a complex trace infrastructure.

866 TWP has a very uniform packet structure that is optimized for encoding and decoding interleaved byte
867 streams. The protocol can be implemented easily in HW and the ability to switch active trace streams on
868 any byte boundary decreases the amount of buffering required to support frame creation. The fixed data
869 frame also simplifies mapping TWP to some other transport protocol payload (the GbT scenario). TWP is
870 thus ideal for trace data paths where many high-bandwidth trace sources are merged before export on a
871 high-performance link.

872 These high-throughput requirements extend into the DTS as well. The fixed frames of TWP enable efficient
873 decode of the captured trace stream. The DTC hardware can remove lower-level link maintenance packets
874 (synchronization and padding) before the higher-level data is stored. This type of filtering is highly
875 desirable when supporting systems where constraints dictate that the trace interface cannot be halted (e.g., a
876 multi-point data mode PTI).

877 While STP also supports merging of trace streams, the protocol also provides features that assist high-level
878 trace protocol (e.g. time stamps, frame markers, and hierarchical source IDs). These features greatly
879 decrease the complexity at the trace source. These sources do not have to worry about supporting their own
880 methods of time stamping or frame marking within their own protocols. The hierarchical IDs enable
881 support for complex trace topologies (e.g., software message traces from multiple processes on multiple
882 CPUs). Supporting these features increases the complexity of a module merging the data from various
883 sources into an STP stream. Since the interleaving boundary for STP is the non-fixed STP message
884 boundary, the modules implementing STP might require significant buffering and pipelining to achieve
885 high throughput. STP is thus ideal for trace data paths that might not have extreme bandwidth requirements
886 but support many trace sources (such as SW threads or small HW modules) generating trace.

887 **Figure 30** shows an example of a DIVS architecture that uses the various MIPI protocols and specifications
 888 in a layered approach to trace export. SW and HW messages, encoded as STP messages (comprised of STP
 889 packets) are transferred on the trace interconnect. High-bandwidth processor trace byte streams are also
 890 present on this interconnect. These various trace byte streams are interleaved using TWP and the packets
 891 are either exported directly to the pins or collected into GbT Network Messages for adaptation to a
 892 functional network protocol.



893

Figure 30 Example Trace Architecture

7.6 System Software Trace (SyS-T) Specification

7.6.1 Overview

894 System Software Trace (SyS-T) is a format for transporting software traces and debugging information
 895 between a target system (TS) running embedded software, and a debug and test system (DTS), typically a
 896 computer running one or more debug and test applications (debuggers and trace tools). SyS-T is primary an
 897 OS independent software tracing protocol, but it can also be used on bare-metal or OS environments.

898 The purpose of SyS-T is to provide a common trace format to exchange information between a TS and a
 899 DTS. SoCs contain many different software agents. For different operating systems there exist different,
 900 specific tracing solutions. There is no common solution existing across different software/firmware and
 901 hardware agents. MIPI SyS-T is aiming to fill this gap.

7.6.2 Relationship to MIPI Debug Architecture

902 **Figure 31** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
 903 SyS-T specification.

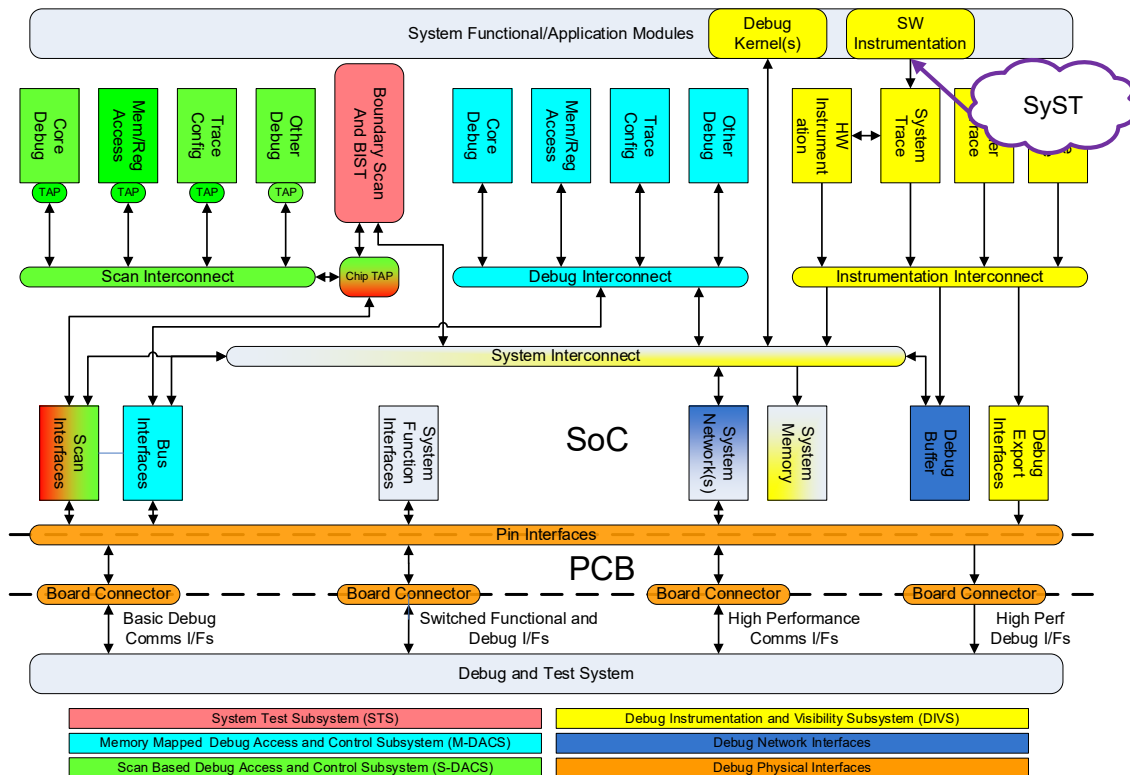
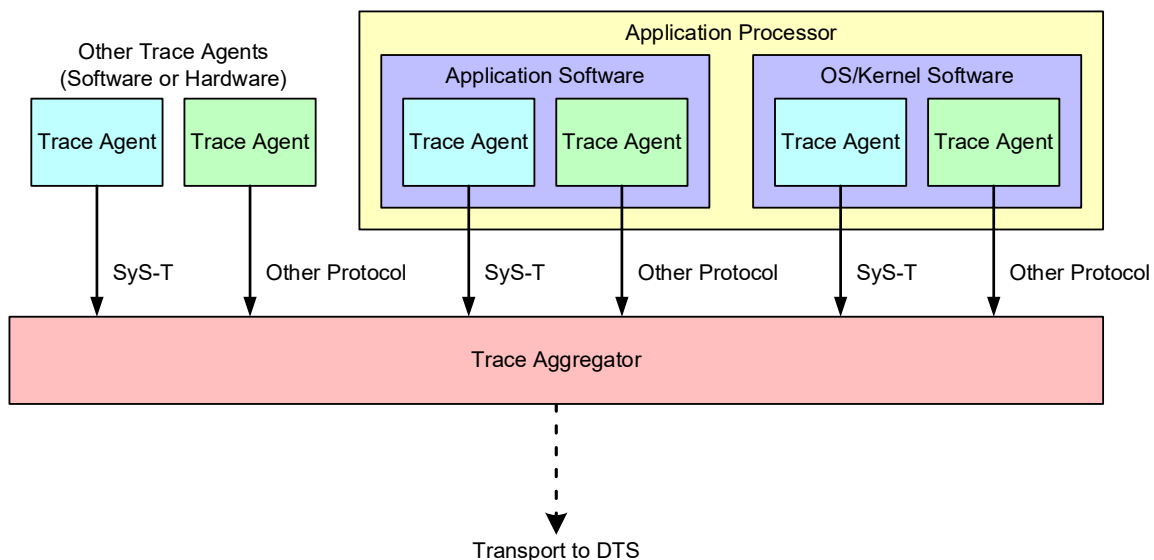


Figure 31 SyS-T in the MIPI Debug Architecture

7.6.3 Usage

905 SyS-T provides a platform independent general purpose trace protocol and software instrumentation library.
 906 SyS-T defines a variety of trace messages ranging from simple UTF-8 based text and printf() style
 907 messages to complex binary data payloads. SyS-T is suitable for trace data generation from non-OS, bare-
 908 metal environments, as well as OS kernel and user mode software. The SyS-T specification enables vendor
 909 independent trace debug tools development for environments that don't already provide an established trace
 910 standard. It does so by separating the trace generation on the TS from the decoding on the DTS into
 911 independent tasks.

912 Today's platforms or SoCs contain multiple agents that are producing traces send from a TS. Different
 913 agents can be seen as independent from each other regarding trace generation. Additional logic like a trace
 914 arbiter is used to combine the agents trace data fragments together into a single platform level data stream.
 915 SyS-T does not replace the trace arbiter step. SyS-T is used directly inside the agents for generating the
 916 SyS-T trace data the gets send to the trace arbiter. A system implementing SyS-T therefore owns one to
 917 many independent SyS-T instances, depending on how many agents are using the SyS-T tracing method.



918

Figure 32 SyS-T Instances in a Target System

7.6.4 SyS-T Instrumentation Library

919 The SyS-T Data Protocol generation is provided by a portable “C”-Language based software library called
 920 SyS-T Instrumentation Library [MIPIII]. The SyS-T Instrumentation Library provides a function style API
 921 (referred to as the SyS-T API) to software using pre-processor macros. This library serves as the reference
 922 implementation for a SyS-T Data Protocol generator. The usage of this library is optional. Vendor-specific
 923 implementations are allowed as long as the output is compatible with the SyS-T Data Protocol.

7.6.5 Detailed Specification

924 In addition to the current version 1.0 of the MIPI SyS-T Specification, version 1.1, is under development in
925 the MIPI Debug Working Group and is expected to be available in 2021. Version 1.1 will include an
926 additional MIPI SyS-T packet type to support sending pure binary data packets.

927 For details of SyS-T technology, consult: MIPI Alliance Specification for System Software Trace (SyS-T),
928 *[MIP110]*. This specification is available to MIPI members and to the public through the MIPI website. The
929 public version of the specification can be found at: <http://resources.mipi.org/mipi-sys-t-download>. In
930 addition to the specification, the Open Source code for the SyS-T Instrumentation Library with an example
931 implementation is posted on GitHub, *[MIP111]*.

This page intentionally left blank.

8 Debug Network Interfaces (DNI)

8.1 Gigabit Debug (GbD) Specification

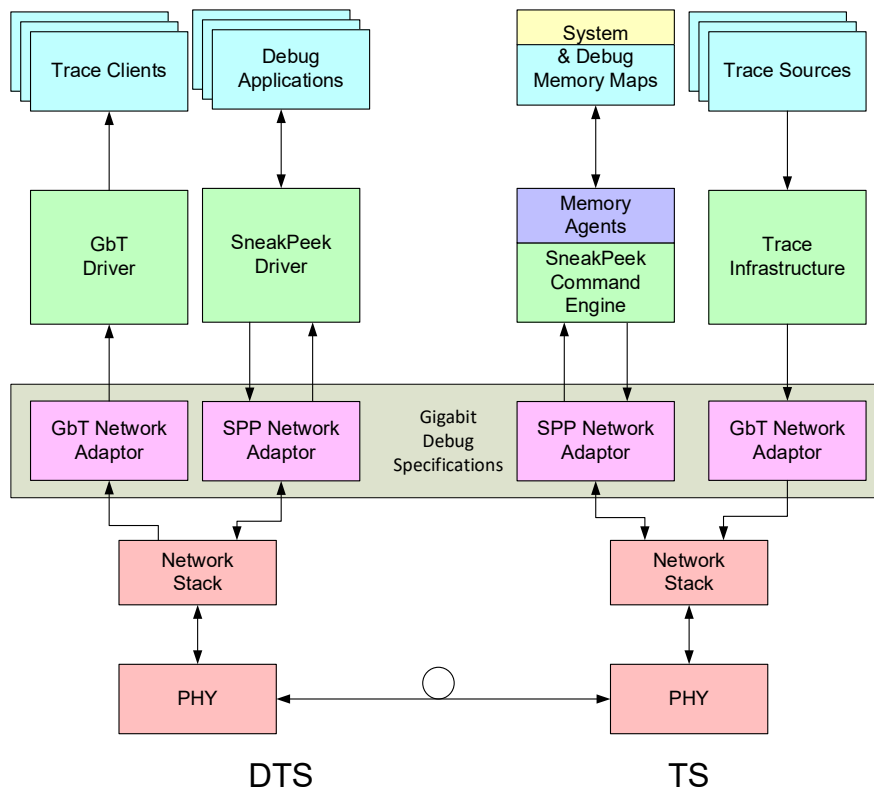
8.1.1 Overview

932 Gigabit Debug (GbD) is the blanket terminology for mapping debug capabilities to a particular functional
933 network. Unlike NIDnT, the network interface and protocol stack function normally. Gigabit Debug just
934 defines how to adapt the SneakPeek and Gigabit Trace functions so that they can co-exist with other
935 network traffic (as normal application layer functions). While the goal of a GbD system is to minimize
936 intrusiveness of debug on regular system functions, it is acknowledged that some debug capabilities (like
937 trace) may require significant network bandwidth and will thus have the potential for significant impact to
938 the normal system.

939 The current effort focuses on mapping the network independent MIPI SneakPeek Protocol and Gigabit
940 Trace framework to networks commonly found in many systems. Some of the items addressed in Gigabit
941 Debug Specifications include:

- 942 • Connection/session initialization and de-initialization
- 943 • Network link management
- 944 • Packaging of MIPI protocol messages into network messages
- 945 • Mapping aspects of Basic Debug and Trace functionality to network features
- 946 • Network error handling

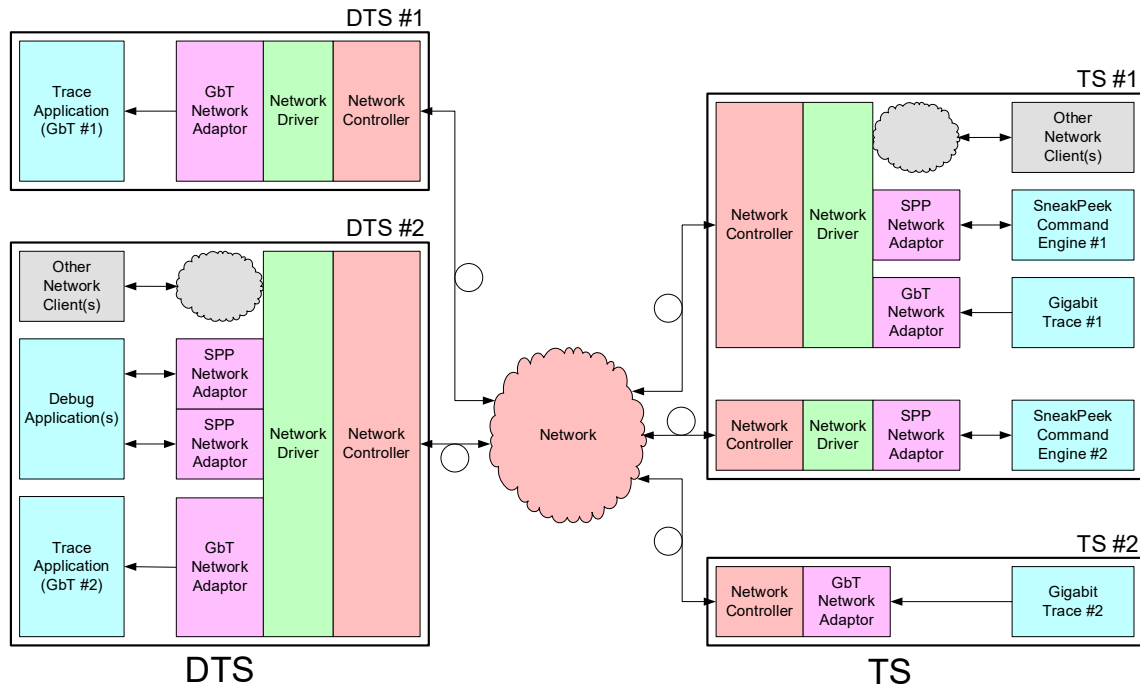
947 **Figure 33** shows how the Gigabit Debug Adaptor specifications complement the specific MIPI debug
948 protocol specifications.



949

Figure 33 Gigabit Debug Functional Block Diagram

950 One of the fundamental features of GbD functionality is that it co-exists with non-debug network clients
 951 and can operate quite effectively in multi-node networks that are commonplace today. **Figure 34** illustrates
 952 how GbD and non-debug network traffic are integrated in such networks.

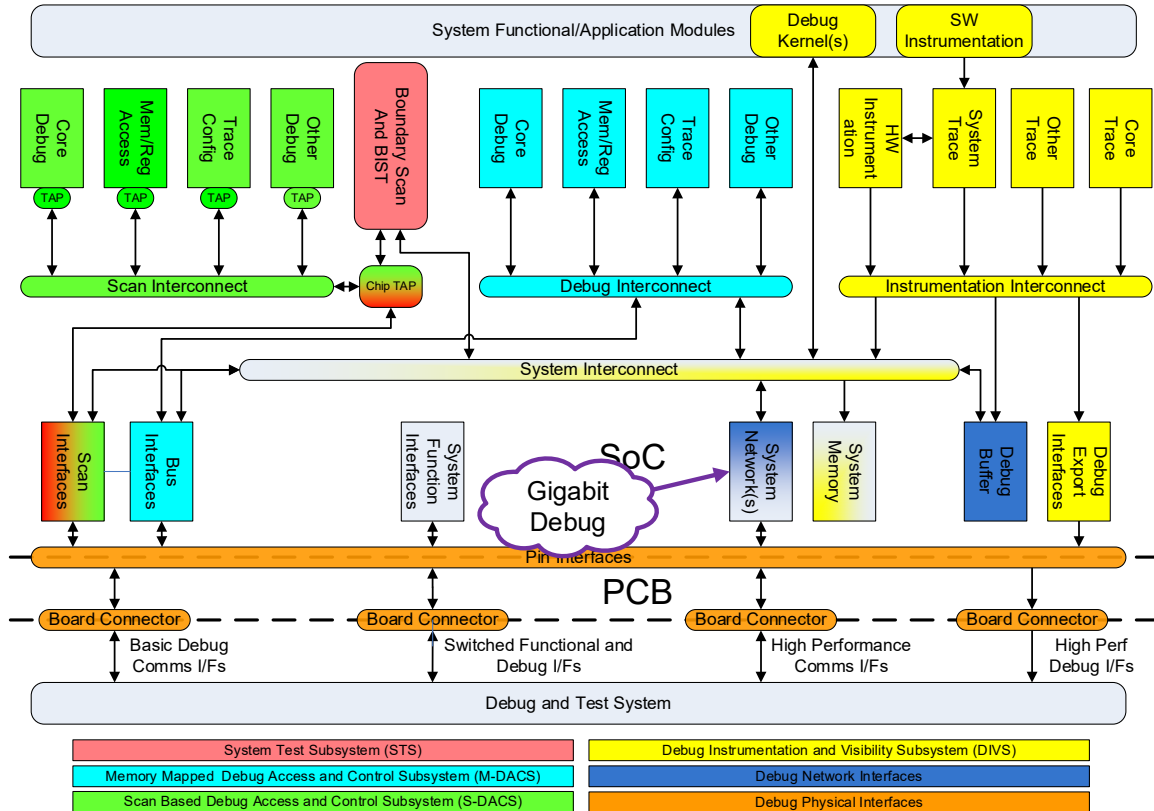


953

Figure 34 GbD in a Multiple-Node Network

8.1.2 Relationship to MIPI Debug Architecture

954 **Figure 35** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
955 Gigabit Debug specifications.



956

Figure 35 Gigabit Debug and the MIPI Architecture

8.1.3 Detailed Specifications

957 Currently, the Gigabit Debug Specification addresses the following functional networks:

- 958
- 959 • USB
 - 960 • For details of the Gigabit Debug adaptors for USB, consult the document: MIPI Alliance
961 Specification for Gigabit Debug for USB, **[MIPI07]**. This specification is available to MIPI
962 members and to the public through the MIPI website. The public version of the specification can
963 be found at: <http://resources.mipi.org/mipi-gbd-usb-download>.
 - 964 • Supports both a MIPI-defined extension to standard USB Descriptors and the Debug Device
965 Class Descriptor as given by the Device Class Specification for Debug, **[USB01]**.
 - 966 • TCP and UDP over Internet Protocols
 - 967 • For details of the Gigabit Debug adaptors for Internet Protocol (IP) sockets, consult the
968 document: MIPI Alliance Specification for Gigabit Debug for Internet Protocol Sockets,
969 **[MIPI08]**. This specification is available to MIPI members and to the public through the MIPI
970 website. The public version of the specification can be found at: <http://resources.mipi.org/mipi-gigabit-debug-for-ips-download>.

971 Other functional networks will be addressed in future Gigabit Debug Specifications.

8.2 Debug for I3C

8.2.1 Overview

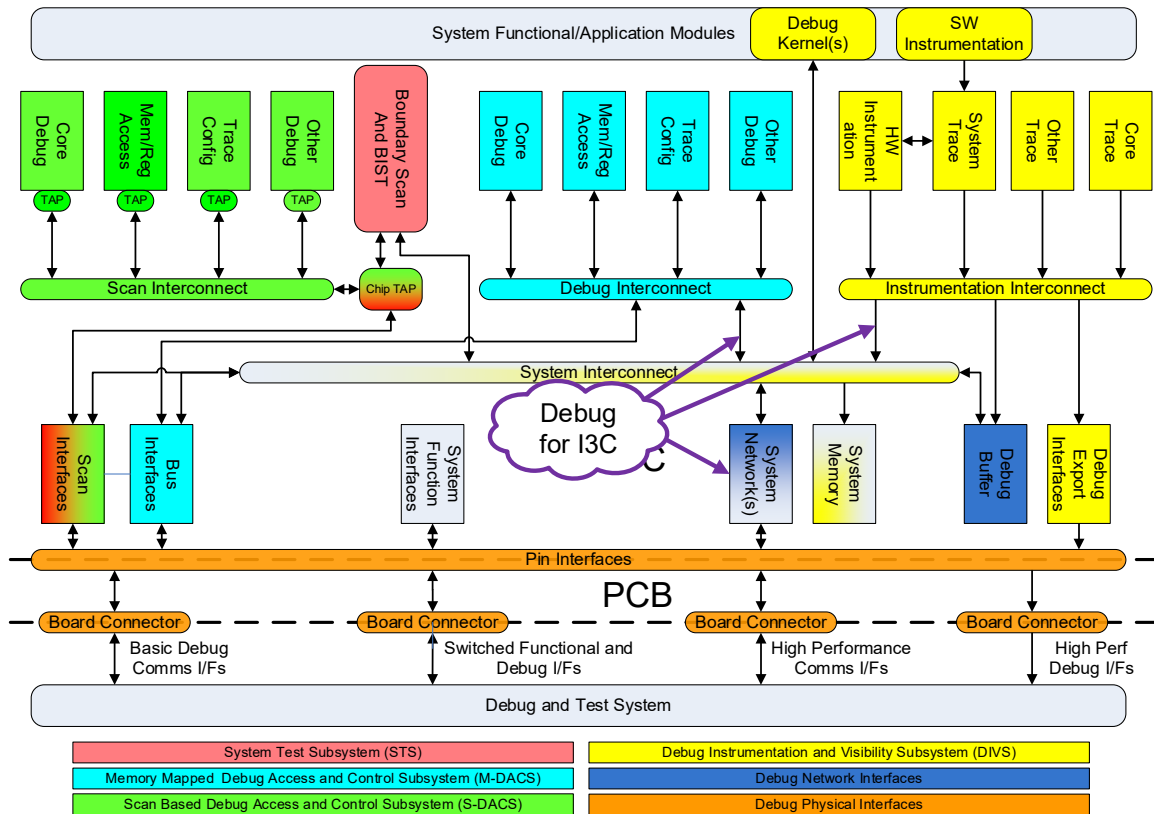
972 The Debug for I3C Specification describes methods for using the Improved Inter Integrated Circuit (I3C) as
973 a minimal-pin interface to transport debug controls and data between a DTS and a TS. Current debug
974 solutions, such as JTAG [*IEEE01*] and Arm® Serial Wire Debug [*ARM01*], are statically structured which
975 leads to limited scalability regarding the accessibility of debug components/devices. Also, when looking at
976 the new requirements of near future technologies, such as 5G, and environments/markets, such as IoT, there
977 are gaps that need to be addressed. The Debug for I3C Specification targets these gaps and shortcomings by
978 using the capabilities of I3C to handle debug connectivity on buses that are dedicated for debug or shared
979 with functional transfers, handling the debug network topology in a dynamic fashion.

980 The Debug for I3C Specification is designed in accordance with either v1.0 or greater of the MIPI
981 Specification for I3C [*MIPI13*], or v1.0 or greater of the I3C Basic Specification [*MIPI14*].
982 Implementations can be used with I3C interfaces that implement either specifications. The Debug for I3C
983 Specification relies on the multi-controlling and multi-drop capabilities of the I3C Specification. The
984 Debug for I3C Specification uses the existing common command codes (CCC) as defined by [*MIPI13*] as
985 well as defining debug-specific CCC to handle debug communication and trace messaging. In-band
986 interrupts (IBI) are also used and debug-specific Mandatory Data Byte (MDB) values are defined as a
987 method of debug event and other communications initiated by the TS.

988 The Debug for I3C Specification allows for different designs where the I3C bus could be shared with non-
989 debug communication. Whether the I3C bus is shared or dedicated for debug, the specification also allows
990 for different DTS access points and allows for an externally connected DTS. The ability for an I3C bus to
991 have multiple Controller-capable devices allows the DTS to be connected as either the Primary Controller
992 (usually with dedicated debug I3C buses) or as a Secondary Controller (usually with shared I3C buses).

8.2.2 Relationship to MIPI Debug Architecture

993 **Figure 36** shows the standard MIPI debug architecture highlighting the functional areas addressed by the
994 Debug for I3C Specification.



995 **Figure 36 Debug for I3C in the MIPI Debug Architecture**

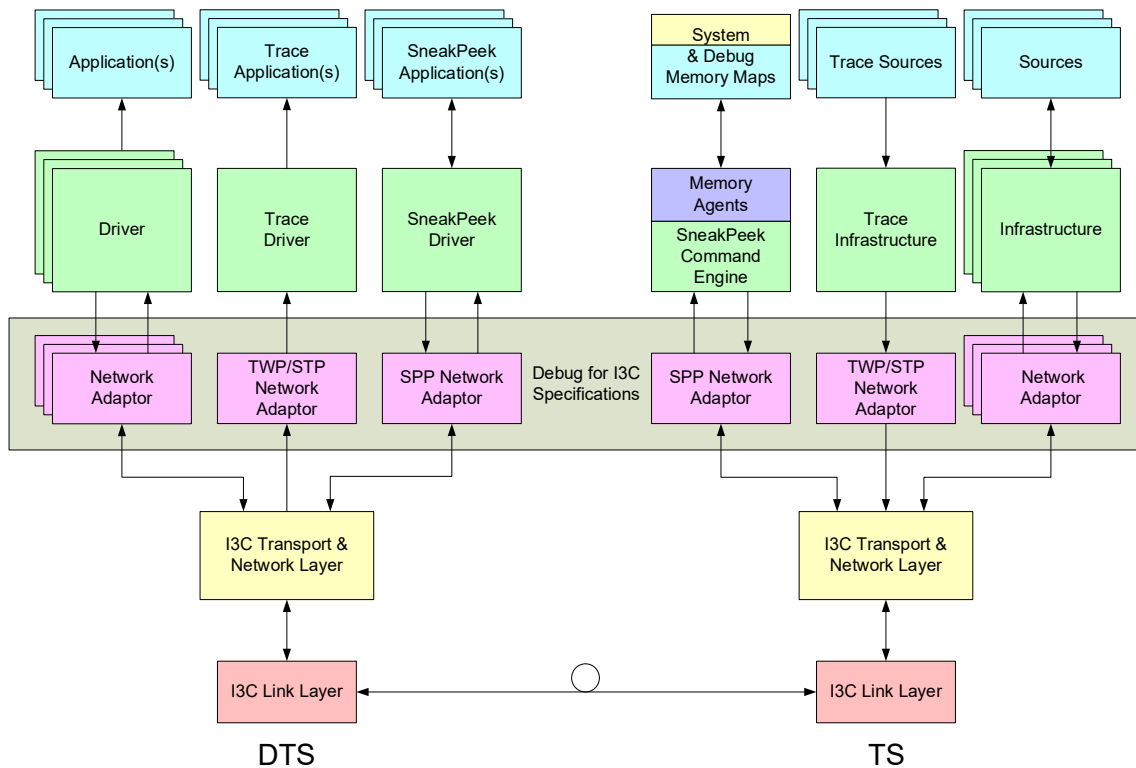
8.2.3 Target System Implementation Overview

996 The Debug for I3C Specification allows for variations of adaptors for the different debug protocols. This
997 specification maps the following protocols:

- 998 • **SneakPeek:** Used for debug communication with a SneakPeek Command Engine (TinySPP).
- 999 • **TWP:** Used for output of trace formatted using Trace Wrapper Protocol.
- 1000 • **STP:** Used for output of trace formatted using System Trace Protocol.
- 1001 • **Simplified Address-Mapped (SAM):** Simple address-mapped access to TS resources.
- 1002 • **UART:** Virtual UART for character-oriented communication, e.g., `scanf()` and `printf()`, or a
1003 GDB debug monitor.
- 1004 • **ImpDef:** Implementation-Defined communication protocol.

1005 The primary function of these adaptors (referred to as a Network Adaptor) is facilitating the transport of
1006 data between debug application layer entities at opposite ends of an I3C bus. The Network Adaptor maps
1007 data objects that have meaning at the debug application layer to transport mechanisms provided by an I3C
1008 bus. The Network Adaptor takes data from a debug application layer function and passes it to an I3C
1009 protocol stack, or vice versa. This mapping preserves the relevant properties of the application data. A
1010 Network Adaptor also provides control functions connected with system setup, initialization, and operation.

1011 **Figure 37** shows how the Debug for I3C Specification complements the specific MIPI debug protocol
 1012 specifications with Applications and Debug Protocols above it, and I3C transport networks below it.



1013

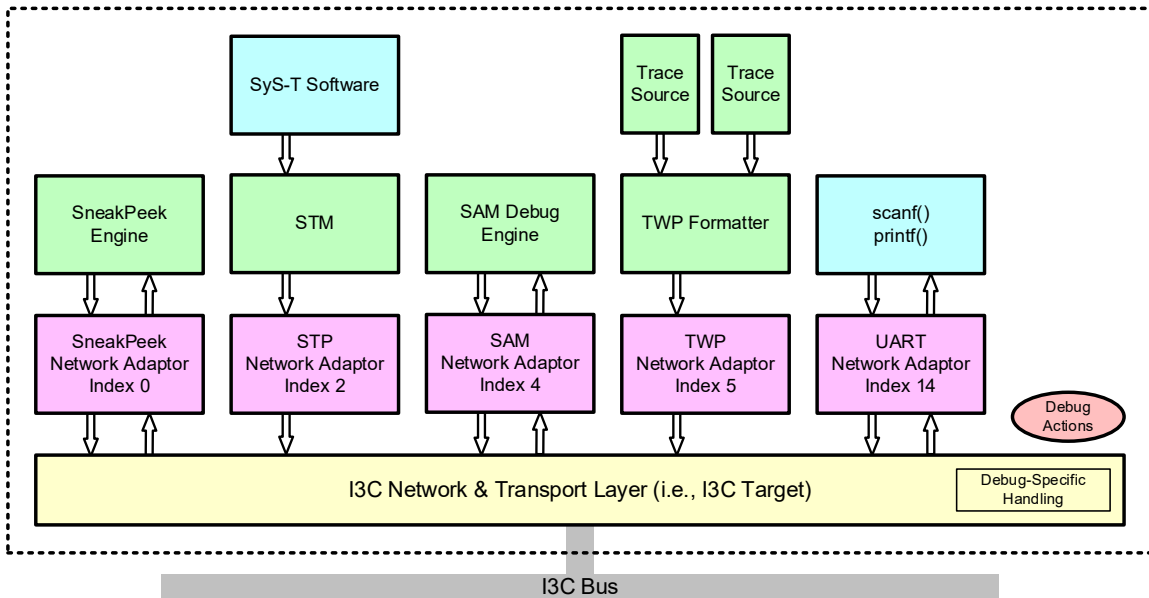
Figure 37 Debug for I3C Functional Block Diagram

1014 **Figure 38** shows an example Target System. This figure shows the standard I3C Target behavior (colored
 1015 yellow), the global debug functions (colored red), four Network Adaptors (colored purple), and the
 1016 accompanying debug functions (colored green for functions that are typically hardware and blue for those
 1017 that are typically software).

1018 The Network Adaptors in this system are:

- 1019 • Index 0 is a SneakPeek Protocol (SPP) Network Adaptor transporting bytes formatted as
 1020 Command and Response Packets for a Command Engine using the TinySPP style.
- 1021 • Index 2 is a System Trace Protocol (STP) Network Adaptor transporting data from an STM which
 1022 contains trace produced by a SyS-T client.
- 1023 • Index 4 is a Simplified Address-Mapped (SAM) Network Adaptor transporting bytes formatted as
 1024 Commands and Responses for a Debug Engine using the SAM Protocol.

- 1025 • Index 5 is a Trace Wrapper Protocol (TWP) Network Adaptor transporting trace data from two
1026 trace sources that has been combined into a single stream using TWP.
- 1027 • Index 14 is a UART Network Adaptor carrying character streams to and from `scanf()` and
1028 `printf()` functions in an application program.



1029

Figure 38 Example Target System with Multiple Network Adaptors

8.2.4 Detailed Specification

1030 For details of the MIPI Debug for I3C, consult the document: MIPI Alliance Specification for Debug for
1031 I3C, [MIPI12]. This specification is available to MIPI members and to the public through the MIPI
1032 website. The public version of the specification can be found at: [https://resources.mipi.org/mipi-debug-i3c-](https://resources.mipi.org/mipi-debug-i3c-download)
1033 [download](https://resources.mipi.org/mipi-debug-i3c-download).

This page intentionally left blank.

Participants

The following list includes those persons who participated in the Working Group that developed this Supporting Document and who consented to appear on this list.

Bruce Ableidinger, SiFive
Christian Boenig, Lauterbach GmbH
Enrico Carrieri, Intel Corporation
Gary Cooper, Texas Instruments Incorporated
John Horley, Arm Limited
Jason Kirschenbaum, Intel Corporation
Rolf Kuehnis, Intel Corporation

Stephan Lauterbach, Lauterbach GmbH
Jason Peck, Texas Instruments Incorporated
Radu Pitigoi-Aron, Qualcomm Incorporated
Matthew Schnoor, Intel Corporation
Eric Upson, Intel Corporation
Dan Wetzel, Western Digital Technologies, Inc.

Past contributors to v1.2:

Eddie Ashfield, MIPI Alliance (Staff)
Enrico Carrieri, Intel Corporation
Gary Cooper, Texas Instruments Incorporated
Patrik Eder, Intel Corporation
John Horley, ARM Limited
Rolf Kuehnis, Intel Corporation

Stephan Lauterbach, Lauterbach GmbH
Andrea Martin, Lauterbach GmbH
Laura Nixon, MIPI Alliance (Staff)
Jason Peck, Texas Instruments Incorporated
Norbert Schulz, Intel Corporation

This page intentionally left blank.